XL232-512-FB374 Datasheet

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# 1 xCORE Multicore Microcontrollers

The xCORE200 Series is a comprehensive range of 32-bit multicore microcontrollers that brings the low latency and timing determinism of the xCORE architecture to mainstream embedded applications. Unlike conventional microcontrollers, xCORE multicore microcontrollers execute multiple real-time tasks simultaneously and communicate between tasks using a high speed network. Because xCORE multicore microcontrollers are completely deterministic, you can write software to implement functions that traditionally require dedicated hardware.

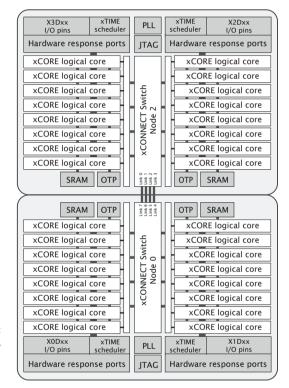


Figure 1: XL232-512-FB374 block diagram

Key features of the XL232-512-FB374 include:

- ► **Tiles**: Devices consist of one or more xCORE tiles. Each tile contains between five and eight 32-bit xCOREs with highly integrated I/O and on-chip memory.
- Logical cores Each logical core can execute tasks such as computational code, DSP code, control software (including logic decisions and executing a state machine) or software that handles I/O. Section 6.1
- xTIME scheduler The xTIME scheduler performs functions similar to an RTOS, in hardware. It services and synchronizes events in a core, so there is no requirement for interrupt handler routines. The xTIME scheduler triggers cores

on events generated by hardware resources such as the I/O pins, communication channels and timers. Once triggered, a core runs independently and concurrently to other cores, until it pauses to wait for more events. Section 6.2

- Channels and channel ends Tasks running on logical cores communicate using channels formed between two channel ends. Data can be passed synchronously or asynchronously between the channel ends assigned to the communicating tasks. Section 6.5
- xCONNECT Switch and Links Between tiles, channel communications are implemented over a high performance network of xCONNECT Links and routed through a hardware xCONNECT Switch. Section 6.6
- ▶ **Ports** The I/O pins are connected to the processing cores by Hardware Response ports. The port logic can drive its pins high and low, or it can sample the value on its pins optionally waiting for a particular condition. Section 6.3
- Clock blocks xCORE devices include a set of programmable clock blocks that can be used to govern the rate at which ports execute. Section 6.4
- Memory Each xCORE Tile integrates a bank of SRAM for instructions and data, and a block of one-time programmable (OTP) memory that can be configured for system wide security features. Section 9
- PLL The PLL is used to create a high-speed processor clock given a low speed external oscillator. Section 7
- ▶ JTAG The JTAG module can be used for loading programs, boundary scan testing, in-circuit source-level debugging and programming the OTP memory. Section 10

### 1.1 Software

Devices are programmed using C, C++ or xC (C with multicore extensions). XMOS provides tested and proven software libraries, which allow you to quickly add interface and processor functionality such as USB, Ethernet, PWM, graphics driver, and audio EQ to your applications.

### 1.2 xTIMEcomposer Studio

The xTIMEcomposer Studio development environment provides all the tools you need to write and debug your programs, profile your application, and write images into flash memory or OTP memory on the device. Because xCORE devices operate deterministically, they can be simulated like hardware within xTIMEcomposer: uniquely in the embedded world, xTIMEcomposer Studio therefore includes a static timing analyzer, cycle-accurate simulator, and high-speed in-circuit instrumentation.

xTIMEcomposer can be driven from either a graphical development environment, or the command line. The tools are supported on Windows, Linux and MacOS X and available at no cost from xmos.com/downloads. Information on using the tools is provided in the xTIMEcomposer User Guide, X3766.

# 2 XL232-512-FB374 Features

#### ► Multicore Microcontroller with Advanced Multi-Core RISC Architecture

- 32 real-time logical cores on 4 xCORE tiles
- Cores share up to 2000 MIPS
  - Up to 4000 MIPS in dual issue mode
- Each logical core has:
  - Guaranteed throughput of between 1/5 and 1/8 of tile MIPS
  - 16x32bit dedicated registers
- 167 high-density 16/32-bit instructions
  - All have single clock-cycle execution (except for divide)
  - 32x32 $\rightarrow$ 64-bit MAC instructions for DSP, arithmetic and user-definable cryptographic functions

### Programmable I/O

- 256 general-purpose I/O pins, configurable as input or output
  - Up to 56 x 1bit port, 22 x 4bit port, 13 x 8bit port, 6 x 16bit port, 4 x 32bit port 8 xCONNECT links
- Port sampling rates of up to 60 MHz with respect to an external clock
- 128 channel ends (32 per tile) for communication with other cores, on or off-chip

#### Memory

- 512KB internal single-cycle SRAM (max 128KB per tile) for code and data storage
- 32KB internal OTP (max 8KB per tile) for application boot code

#### Hardware resources

- 24 clock blocks (6 per tile)
- 40 timers (10 per tile)
- 16 locks (4 per tile)
- JTAG Module for On-Chip Debug

### Security Features

• Programming lock disables debug and prevents read-back of memory contents

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- AES bootloader ensures secrecy of IP held on external flash memory
- Ambient Temperature Range
  - Commercial qualification: 0°C to 70°C
  - Industrial qualification: -40 °C to 85 °C
- Speed Grade
  - 40: 2000 MIPS
- Power Consumption
  - 1140 mA (typical)
- ▶ 374-pin FBGA package 0.8 mm pitch

# 3 Pin Configuration

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21
A	GND	VDDIO	X1D11	X1D32	X1D26		X1D41	X0D31	X0D29	ты	VDDIO	CLK	TDO	45 X3D32	X3D30		X2D31	X2D29	X2D32	VDDIO	GND
в	X0D37 X,42	X0D36	X1D10	X1D33	X1027	X1D42	X1D40	XODSO	X0D28	X2D36	GND	RST_N	тск	X3D33	X3D31	X3D27	X2D30	X2D28	X2D27 X/27	X2D26 X(2)	<b>Х2Д35</b> ×,17
с	X0D39	X0D38 X(J2)	VDD	X1D30	X1D28	X1D43	GND	X0D33	X0D32	MODE1	OTP VCC	TRST_N	X3D10	к <sup>ар</sup> ХЗД29	GND	x3D43	x3D41	X2D33	VDD	X2D25	х <mark>2D34</mark> х <sub>2</sub> с;
D	X0D41 X,c_1	X0D40 X,L_1	1К X1D34 X <sub>1</sub> C <sub>0</sub>	X1031	X1D29	GND	VDDIO	NC	DEBUG_ N	MODE0		TMS	X3D11	X3D28	X3D26	X3D42	X3D40	22A X2D70 X,L_1	X3D00 X,C	10 X3D01 X(2)	X2D24 X47
E	X0D43	00 X0D42 X,42	X1D35 X,22	VDD	VDD	GND	VDDIO	VDD	VDD				VDD	VDD	VDDIO	GND	VDD	VDD	22A X2D69 X,22	ал X3D08 Х,с?	ал X3D09 <sub>X,L</sub> 9
F	X1D36	VDDIO	GND	VDD	VDD	VDD	VDD	VDD	VDD	PLL AGND	PLL AVDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	GND	VDDIO	200A X2D68 X <sub>2</sub> L <sup>2</sup> <sub>0</sub>
G	X1D49	X1D50 X(1);	X1D51 X_1C	NC	NC	NC	NC	NC	NC				NC	NC	NC	NC	NC	NG	22A X2D67 X,JC	22A X2D66 X jrs	220A X2D65 X <sub>2</sub> L <sup>0</sup> <sub>0</sub>
н	X1D53 X,C,	X1D52 X(L)	VDD																VDD	22A X2D63 X(L)	220A X2D64 X(1) <sup>2</sup>
J	X1D54 X,17	22A X1D55 X <sub>1</sub> L <sup>*</sup>	VDD		GND	GND	GND	GND	GND				GND	GND	GND	GND	GND		VDD	224 X2D62 X,42	220A X2D61 X <sub>1</sub> L <sup>0</sup>
к	X1D58	X1057 X1057	X1D56		GND	GND	GND	GND	GND				GND	GND	GND	GND	GND		22A X2D56 X,2%	22A X2D57 X p <sup>2</sup> 1 X p <sup>2</sup> 1	20A X2D58 × <sub>j</sub> z <sub>5</sub> *
L	VDDIO	GND	$\overset{22A}{\underset{X_{1}L_{2}^{2}}{\overset{22A}}}$		GND	GND	GND	GND	GND				GND	GND	GND	GND	GND		22A X2D55 X,JC	GND	VDDIO
м	X1D64 X,01	X1D63 X,13	22A X1D62 X,L <sup>2</sup>		GND	GND	GND	GND	GND				GND	GND	GND	GND	GND		22A X2D54 X,2?	22A X2D53 X,4?	220A X2D52 X,L]
N	X1D65 X,12	X1D66 X,12	VDD		GND	GND	GND	GND	GND				GND	GND	GND	GND	GND		VDD	X2D50 X,42	200A X2D51 X <sub>2</sub> L <sup>2</sup>
Р	X1D68 X <sub>1</sub> 2 <sup>22A</sup>	X1D67 X_{(1)}^{22A}	VDD																VDD	40 X3D06 X (2)	40 X3D07 X_jU_1^4
R	X1D69 X <sub>1</sub> 2 <sup>22A</sup>	X1D70 X <sub>1</sub> L <sup>24</sup>	X1D37 X <sub>1</sub> L <sup>10</sup>	NC	NC	NC	NC	NC	NC				NC	NC	NC	NC	NC	NC	X2D49	X3D04 X,c1	40 X3D05 ×,1°,
т	X1D38	VDDIO	GND	VDD	VDD	VDD	USB_ VDD	VDD	VDD	VDD	GND	VDD	VDD	VDD	USB_2_ VDD-	VDD	VDD	VDD	GND	VDDIO	4A X3D03 X <sub>1</sub> L <sup>0</sup>
U	X1D17	X1016 X1216	X1D39 X,2	VDD	VDD	GND	VDDIO	NC	VDD		VDDIO		VDD	VDD	VDDIO	GND	VDD	VDD	NC	X2D19	<b>X3D02</b> × <sub>j</sub> L <sup>0</sup>
v	X1D19 X,5;	X1D18 X1218	<b>X0D01</b> X <sub>1</sub> C <sup>10</sup>	X0D02	X0D08	X0D11	USB_ ID_	X1D14	и Х1D25	X0D21	NC	1H X3D23	x2D05	x2D07	USB_2_ ID	NC	X3D15	X3D21	X2D12	X2D17 X(2)	X2D18 × <sub>j</sub> L <sup>0</sup>
w	X0D10 X(L)	X1D22 X <sub>1</sub> C <sup>1G</sup>	USB VDD33	X0D03	X0D09	USB RTUNE	GND	X1D15	X0D14	X0D12	X0D23	X2D00	x2D04	X2D06	GND	USB 2 RTUNE	X3D14	X3D20	USB_2_ VDD33	X2D23	40 X2D16 X <sub>1</sub> 1
Y	X1D23	X0D00	X0D04	X0D06	X1D12	USB VBUS	X1D24	X1D20	X0D15	X0D13	GND	X2D11	X2D02	X2D08	X3D13	USB 2 VBUS	X2D14	X2D20	X3D24	x2D13	X2D22
AA	GND	VDDIO	X0D05	X0D07	x1D13	USB	USB_ DP	X1D21	X0D20	X0D22	VDDIO	X3D12	X2D03	X2D09	USB 2_ DM	USB 2_ DP	x2D15	x2D21	X3D25	VDDIO	GND

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# 4 Signal Description

This section lists the signals and I/O pins available on the XL232-512-FB374. The device provides a combination of 1 bit, 4bit, 8bit and 16bit ports, as well as wider ports that are fully or partially (gray) bonded out. All pins of a port provide either output or input, but signals in different directions cannot be mapped onto the same port.

Pins may have one or more of the following properties:

- PD/PU: The IO pin has a weak pull-down or pull-up resistor. The resistor is enabled during and after reset. Enabling a link or port that uses the pin disables the resistor. Thereafter, the resistor can be enabled or disabled under software control. The resistor is designed to ensure defined logic input state for unconnected pins. It should not be used to pull external circuitry. Note that the resistors are highly non-linear and only a maximum pull current is specified in Section 12.3.
- ST: The IO pin has a Schmitt Trigger on its input.

Power pins (12)									
Signal	Function	Туре	Properties						
GND	Digital ground	GND							
OTP_VCC	OTP power supply	PWR							
PLL_AGND	Analog ground for PLL	PWR							
PLL_AVDD	Analog PLL power	PWR							
USB_2_VDD	Digital tile power	PWR							
USB_2_VDD33	USB Analog power	PWR							
USB_VDD	Digital tile power	PWR							
USB_VDD33	USB Analog power	PWR							
VDD	Digital tile power	PWR							
VDDIO	Digital I/O power	PWR							
VDDIOT_0		PWR							
VDDIOT_1		PWR							

▶ IO: the pin is powered from VDDIO

	JTAG pins (6)		
Signal	Function	Туре	Properties
RST_N	Global reset input	Input	IO, PU, ST
ТСК	Test clock	Input	IO, PD, ST
TDI	Test data input	Input	IO, PU
TDO	Test data output	Output	IO, PD
TMS	Test mode select	Input	IO, PU
TRST_N	Test reset input	Input	IO, PU, ST

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			1/0	) pins	(176)			
Signal	Function						Туре	Properties
X0D00		1A <sup>0</sup>					I/O	IO, PD
X0D01	X <sub>0</sub> L3 <sup>2</sup> <sub>out</sub>	1 B <sup>0</sup>					I/O	IO, PD
X0D02			4A <sup>0</sup>	8A <sup>0</sup>	16A <sup>0</sup>	32A <sup>20</sup>	I/O	IO, PD
X0D03			4A <sup>1</sup>	8A <sup>1</sup>	16A <sup>1</sup>	32A <sup>21</sup>	I/0	IO, PD
X0D04			4B <sup>0</sup>	8A <sup>2</sup>	16A <sup>2</sup>	32A <sup>22</sup>	I/0	IO, PD
X0D05			4B <sup>1</sup>	8A <sup>3</sup>	16A <sup>3</sup>	32A <sup>23</sup>	I/0	IO, PD
X0D06			4B <sup>2</sup>	8A <sup>4</sup>	16A <sup>4</sup>	32A <sup>24</sup>	I/O	IO, PD
X0D07			4B <sup>3</sup>	8A <sup>5</sup>	16A <sup>5</sup>	32A <sup>25</sup>	I/O	IO, PD
X0D08			4A <sup>2</sup>	8A <sup>6</sup>	16A <sup>6</sup>	32A <sup>26</sup>	I/O	IO, PD
X0D09			4A <sup>3</sup>	8A <sup>7</sup>	16A <sup>7</sup>	32A <sup>27</sup>	I/0	IO, PD
X0D10	X <sub>0</sub> L3 <sup>3</sup> <sub>out</sub>	1C <sup>0</sup>					I/O	IO, PD
X0D11		1D <sup>0</sup>					I/O	IO, PD
X0D12		1 E <sup>0</sup>					I/O	IO, PD
X0D13		1F <sup>0</sup>					I/O	IO, PD
X0D14			4C <sup>0</sup>	8B <sup>0</sup>	16A <sup>8</sup>	32A <sup>28</sup>	I/O	IO, PD
X0D15			4C <sup>1</sup>	8B1	16A <sup>9</sup>	32A <sup>29</sup>	I/O	IO, PD
X0D20			4C <sup>2</sup>	8B <sup>6</sup>	16A <sup>14</sup>	32A <sup>30</sup>	I/O	IO, PD
X0D21			4C <sup>3</sup>	8B <sup>7</sup>	16A <sup>15</sup>	32A <sup>31</sup>	I/O	IO, PD
X0D22		1G <sup>0</sup>					I/O	IO, PD
X0D23		1H <sup>0</sup>					I/O	IO, PD
X0D28			4F <sup>0</sup>	8C <sup>2</sup>	16B <sup>2</sup>		I/O	IO, PD
X0D29			4F <sup>1</sup>	8C <sup>3</sup>	16B <sup>3</sup>		I/O	IO, PD
X0D30			4F <sup>2</sup>	8C <sup>4</sup>	16B <sup>4</sup>		I/O	IO, PD
X0D31			4F <sup>3</sup>	8C <sup>5</sup>	16B <sup>5</sup>		I/O	IO, PD
X0D32			4E <sup>2</sup>	8C <sup>6</sup>	16B <sup>6</sup>		I/O	IO, PD
X0D33			4E <sup>3</sup>	8C <sup>7</sup>	16B <sup>7</sup>		I/O	IO, PD
X0D36		1 M <sup>0</sup>		8D <sup>0</sup>	16B <sup>8</sup>		I/0	IO, PD
X0D37	X <sub>0</sub> L0 <sup>4</sup> <sub>in</sub>	1N <sup>0</sup>		8D1	16B <sup>9</sup>		I/0	IO, PD
X0D38	X <sub>0</sub> L0 <sup>3</sup> <sub>in</sub>	100		8D <sup>2</sup>	16B <sup>10</sup>		I/0	IO, PD
X0D39	X <sub>0</sub> L0 <sup>2</sup> <sub>in</sub>	1 P <sup>0</sup>		8D <sup>3</sup>	16B <sup>11</sup>		I/0	IO, PD
X0D40	X <sub>0</sub> L0 <sup>1</sup> <sub>in</sub>			8D <sup>4</sup>	16B <sup>12</sup>		I/0	IO, PD
X0D41	X <sub>0</sub> L0 <sup>0</sup> <sub>in</sub>			8D <sup>5</sup>	16B <sup>13</sup>		I/O	IO, PD
X0D42	X <sub>0</sub> L0 <sup>0</sup> <sub>out</sub>			8D <sup>6</sup>	16B <sup>14</sup>		I/O	IO, PD
X0D43	X <sub>0</sub> L0 <sup>1</sup> <sub>out</sub>			8D <sup>7</sup>	16B <sup>15</sup>		I/0	IO, PD
X1D10		1C <sup>0</sup>					I/O	IOT, PD
X1D11		1D <sup>0</sup>					I/O	IOT, PD
X1D12		1 E <sup>0</sup>					I/O	IO, PD
X1D13		1 F <sup>0</sup>					I/O	IO, PD
X1D14			4C <sup>0</sup>	8B <sup>0</sup>	16A <sup>8</sup>	32A <sup>28</sup>	I/O	IO, PD
X1D15			4C <sup>1</sup>	8B1	16A <sup>9</sup>	32A <sup>29</sup>	I/O	IO, PD
X1D16	X <sub>0</sub> L3 <sup>1</sup>		4D <sup>0</sup>	8B <sup>2</sup>	16A <sup>10</sup>		I/O	IO, PD
								(continued)

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Signal	Function					Туре	Properties
X1D17	X <sub>0</sub> L3 <sup>0</sup> <sub>in</sub>	4D <sup>1</sup>	8B <sup>3</sup>	16A <sup>11</sup>		1/0	IO, PD
X1D18	X <sub>0</sub> L3 <sup>0</sup> <sub>out</sub>	4D <sup>2</sup>	8B <sup>4</sup>	16A <sup>12</sup>		I/O	IO, PD
X1D19	X <sub>0</sub> L3 <sup>1</sup> X <sub>0</sub> L3 <sup>1</sup>	4D <sup>3</sup>	8B <sup>5</sup>	16A <sup>13</sup>		1/0	IO, PD
X1D19 X1D20	AULJout	4C <sup>2</sup>	8B <sup>6</sup>	16A <sup>14</sup>	32A <sup>30</sup>	1/0	IO, PD
X1D20 X1D21		4C <sup>3</sup>	8B <sup>7</sup>	16A <sup>15</sup>	32A <sup>31</sup>	I/O	IO, PD
X1D21 X1D22	X <sub>0</sub> L3 <sup>4</sup> <sub>out</sub> 1G <sup>0</sup>	40	00	IUA	JZA	1/0	IO, PD
X1D22	1H <sup>0</sup>					1/0	IO, PD
X1D23 X1D24	110					1/0	IO, PD
X1D24 X1D25	11 <sup>0</sup>					1/0	IO, PD
X1D23 X1D26	IJ	4E <sup>0</sup>	8C <sup>0</sup>	16B <sup>0</sup>		1/0 1/0	IOT, PD
X1D26 X1D27		4E <sup>o</sup>	8C <sup>3</sup>	168°		I/O	IOT, PD
X1D27 X1D28		4E <sup>-</sup>	8C <sup>2</sup>	16B <sup>2</sup>		1/0 1/0	
X1D28 X1D29		4F°	8C- 8C <sup>3</sup>	16B <sup>2</sup>		1/0	IOT, PD
		4F <sup>2</sup>	8C <sup>3</sup>				IOT, PD
X1D30				16B <sup>4</sup>		I/O	IOT, PD
X1D31		4F <sup>3</sup>	8C <sup>5</sup>	16B <sup>5</sup>		I/0	IOT, PD
X1D32		4E <sup>2</sup>	8C <sup>6</sup>	16B <sup>6</sup>		I/0	IOT, PD
X1D33	2 0	4E <sup>3</sup>	8C <sup>7</sup>	16B <sup>7</sup>		I/O	IOT, PD
X1D34	X <sub>0</sub> L0 <sup>2</sup> <sub>out</sub> 1K <sup>0</sup>					I/O	IO, PD
X1D35	X <sub>0</sub> L0 <sup>3</sup> <sub>out</sub> 1L <sup>0</sup>					I/O	IO, PD
X1D36	X <sub>0</sub> L0 <sup>4</sup> <sub>out</sub> 1M <sup>0</sup>		8D <sup>0</sup>	16B <sup>8</sup>		I/O	IO, PD
X1D37	X <sub>0</sub> L3 <sup>4</sup> <sub>in</sub> 1N <sup>0</sup>		8D <sup>1</sup>	16B <sup>9</sup>		I/0	IO, PD
X1D38	X <sub>0</sub> L3 <sup>3</sup> 10 <sup>0</sup>		8D <sup>2</sup>	16B <sup>10</sup>		I/O	IO, PD
X1D39	X <sub>0</sub> L3 <sup>2</sup> <sub>in</sub> 1P <sup>0</sup>		8D <sup>3</sup>	16B <sup>11</sup>		I/O	IO, PD
X1D40			8D <sup>4</sup>	16B <sup>12</sup>		I/O	IOT, PD
X1D41			8D <sup>5</sup>	16B <sup>13</sup>		I/O	IOT, PD
X1D42			8D <sup>6</sup>	16B <sup>14</sup>		I/O	IOT, PD
X1D43			8D <sup>7</sup>	16B <sup>15</sup>		I/O	IOT, PD
X1D49	X <sub>0</sub> L1 <sup>4</sup>				32A <sup>0</sup>	I/O	IO, PD
X1D50	X <sub>0</sub> L1 <sup>3</sup> in				32A <sup>1</sup>	I/O	IO, PD
X1D51	X <sub>0</sub> L1 <sup>2</sup>				32A <sup>2</sup>	I/O	IO, PD
X1D52	X <sub>0</sub> L1 <sup>1</sup>				32A <sup>3</sup>	I/O	IO, PD
X1D53	X <sub>0</sub> L1 <sup>0</sup>				32A <sup>4</sup>	I/O	IO, PD
X1D54	X <sub>0</sub> L1 <sup>0</sup> <sub>out</sub>				32A <sup>5</sup>	I/O	IO, PD
X1D55	X <sub>0</sub> L1 <sup>1</sup> <sub>out</sub>				32A <sup>6</sup>	I/O	IO, PD
X1D56	X <sub>0</sub> L1 <sup>2</sup> <sub>out</sub>				32A <sup>7</sup>	I/O	IO, PD
X1D57	X <sub>0</sub> L1 <sup>3</sup> <sub>out</sub>				32A <sup>8</sup>	I/O	IO, PD
X1D58	X <sub>0</sub> L1 <sup>4</sup> <sub>out</sub>				32A <sup>9</sup>	I/O	IO, PD
X1D61	X <sub>0</sub> L2 <sup>4</sup>				32A <sup>10</sup>	I/0	IO, PD
X1D62	$X_0L2_{in}^3$				32A <sup>11</sup>	I/0	IO, PD
X1D63	X <sub>0</sub> L2 <sup>2</sup> <sub>in</sub>				32A <sup>12</sup>	I/O	IO, PD
X1D64	X <sub>0</sub> L2 <sup>1</sup>				32A <sup>13</sup>	I/O	IO, PD
X1D65	X <sub>0</sub> L2 <sup>0</sup>				32A <sup>14</sup>	I/O	IO, PD
X1D66	X <sub>0</sub> L2 <sup>0</sup> <sub>out</sub>				32A <sup>15</sup>	I/O	IO, PD

XS2-L32A-512-FB374

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Signal	Function			Туре	Properties
X1D67	X <sub>0</sub> L2 <sup>1</sup> <sub>out</sub>		32A <sup>16</sup>	I/O	IO, PD
X1D68	X <sub>0</sub> L2 <sup>2</sup> <sub>out</sub>		32A <sup>17</sup>	I/O	IO, PD
X1D69	X <sub>0</sub> L2 <sup>3</sup> <sub>out</sub>		32A <sup>18</sup>	I/O	IO, PD
X1D70	X <sub>0</sub> L2 <sup>4</sup> <sub>out</sub>		32A <sup>19</sup>	I/O	IO, PD
X2D00	1A <sup>0</sup>			I/O	IO, PD
X2D02		4A <sup>0</sup> 8A <sup>0</sup> 16A	<sup>0</sup> 32A <sup>20</sup>	I/0	IO, PD
X2D03		4A <sup>1</sup> 8A <sup>1</sup> 16A	<sup>1</sup> 32A <sup>21</sup>	I/O	IO, PD
X2D04		4B <sup>0</sup> 8A <sup>2</sup> 16A	<sup>2</sup> 32A <sup>22</sup>	I/O	IO, PD
X2D05		4B <sup>1</sup> 8A <sup>3</sup> 16A	<sup>3</sup> 32A <sup>23</sup>	I/O	IO, PD
X2D06		4B <sup>2</sup> 8A <sup>4</sup> 16A	<sup>4</sup> 32A <sup>24</sup>	I/O	IO, PD
X2D07		4B <sup>3</sup> 8A <sup>5</sup> 16A	<sup>5</sup> 32A <sup>25</sup>	I/0	IO, PD
X2D08		4A <sup>2</sup> 8A <sup>6</sup> 16A	<sup>6</sup> 32A <sup>26</sup>	I/O	IO, PD
X2D09		4A <sup>3</sup> 8A <sup>7</sup> 16A	<sup>7</sup> 32A <sup>27</sup>	I/0	IO, PD
X2D11	1D <sup>0</sup>			I/0	IO, PD
X2D12	1E <sup>0</sup>			I/O	IO, PD
X2D13	1F <sup>0</sup>			I/O	IO, PD
X2D14		4C <sup>0</sup> 8B <sup>0</sup> 16A	<sup>8</sup> 32A <sup>28</sup>	I/O	IO, PD
X2D15		4C <sup>1</sup> 8B <sup>1</sup> 16A	<sup>9</sup> 32A <sup>29</sup>	I/O	IO, PD
X2D16	X <sub>2</sub> L4 <sup>4</sup> <sub>in</sub>	4D <sup>0</sup> 8B <sup>2</sup> 16A	10	I/O	IO, PD
X2D17	X <sub>2</sub> L4 <sup>3</sup> <sub>in</sub>	4D <sup>1</sup> 8B <sup>3</sup> 16A	11	1/0	IO, PD
X2D18	X <sub>2</sub> L4 <sup>2</sup> <sub>in</sub>	4D <sup>2</sup> 8B <sup>4</sup> 16A	12	1/0	IO, PD
X2D19	X <sub>2</sub> L4 <sup>1</sup> <sub>in</sub>	4D <sup>3</sup> 8B <sup>5</sup> 16A	13	1/0	IO, PD
X2D20		4C <sup>2</sup> 8B <sup>6</sup> 16A	<sup>14</sup> 32A <sup>30</sup>	1/0	IO, PD
X2D21		4C <sup>3</sup> 8B <sup>7</sup> 16A	<sup>15</sup> 32A <sup>31</sup>	1/0	IO, PD
X2D22	1G <sup>0</sup>			1/0	IO, PD
X2D23	1H <sup>0</sup>			1/0	IO, PD
X2D24	X <sub>2</sub> L7 <sup>0</sup> 11 <sup>0</sup>			1/0	IO, PD
X2D25	X <sub>2</sub> L7 <sup>0</sup> <sub>out</sub> 1J <sup>0</sup>			1/0	IO, PD
X2D26	X <sub>2</sub> L7 <sup>3</sup> <sub>out</sub>	4E <sup>0</sup> 8C <sup>0</sup> 16B	0	1/0	IO, PD
X2D27	X <sub>2</sub> L7 <sup>4</sup> <sub>out</sub>	4E <sup>1</sup> 8C <sup>1</sup> 16B	1	1/0	IO, PD
X2D28	2 000	4F <sup>0</sup> 8C <sup>2</sup> 16B	2	1/0	IO, PD
X2D29		4F <sup>1</sup> 8C <sup>3</sup> 16B	3	1/0	IO, PD
X2D30		4F <sup>2</sup> 8C <sup>4</sup> 16B	4	1/0	IO, PD
X2D31		4F <sup>3</sup> 8C <sup>5</sup> 16B	5	1/0	IO, PD
X2D32		4E <sup>2</sup> 8C <sup>6</sup> 16B		1/0	IO, PD
X2D33		4E <sup>3</sup> 8C <sup>7</sup> 16B		1/0	IO, PD
X2D34	X <sub>2</sub> L7 <sup>1</sup> 1K <sup>0</sup>			1/0	IO, PD
X2D35	$X_2L7_{out}^2$ 1L <sup>0</sup>			I/O	IO, PD
X2D36	1M <sup>0</sup>	8D <sup>0</sup> 16B	8	1/0	IO, PD
X2D30	X <sub>2</sub> L5 <sup>4</sup>	55 100	32A <sup>0</sup>	I/O	IO, PD
X2D49 X2D50	X <sub>2</sub> L5 <sup>3</sup> <sub>in</sub>		32A <sup>1</sup>	I/O	IO, PD
X2D50	X <sub>2</sub> L5 <sup>2</sup> <sub>in</sub>		32A <sup>2</sup>	I/O	IO, PD
	$X_2L5_{in}^1$		32A <sup>3</sup>	I/O	IO, PD

(continued)

Signal	Function						Туре	Properties
X2D53	X <sub>2</sub> L5 <sup>0</sup>					32A <sup>4</sup>	I/0	IO, PD
X2D54	X <sub>2</sub> L5 <sup>0</sup> <sub>out</sub>					32A <sup>5</sup>	I/0	IO, PD
X2D55	X <sub>2</sub> L5 <sup>1</sup> <sub>out</sub>					32A <sup>6</sup>	I/0	IO, PD
X2D56	X <sub>2</sub> L5 <sup>2</sup> <sub>out</sub>					32A <sup>7</sup>	I/0	IO, PD
X2D57	X <sub>2</sub> L5 <sup>3</sup> <sub>out</sub>					32A <sup>8</sup>	I/0	IO, PD
X2D58	X <sub>2</sub> L5 <sup>4</sup> <sub>out</sub>					32A <sup>9</sup>	I/0	IO, PD
X2D61	X <sub>2</sub> L6 <sup>4</sup> <sub>in</sub>					32A <sup>10</sup>	I/0	IO, PD
X2D62	X <sub>2</sub> L6 <sup>3</sup> <sub>in</sub>					32A <sup>11</sup>	I/0	IO, PD
X2D63	X <sub>2</sub> L6 <sup>2</sup> <sub>in</sub>					32A <sup>12</sup>	I/0	IO, PD
X2D64	X <sub>2</sub> L6 <sup>1</sup>					32A <sup>13</sup>	I/O	IO, PD
X2D65	X <sub>2</sub> L6 <sup>0</sup>					32A <sup>14</sup>	I/O	IO, PD
X2D66	X <sub>2</sub> L6 <sup>0</sup> <sub>out</sub>					32A <sup>15</sup>	I/0	IO, PD
X2D67	X <sub>2</sub> L6 <sup>1</sup> <sub>out</sub>					32A <sup>16</sup>	I/0	IO, PD
X2D68	X <sub>2</sub> L6 <sup>2</sup> <sub>out</sub>					32A <sup>17</sup>	I/0	IO, PD
X2D69	X <sub>2</sub> L6 <sup>3</sup> <sub>out</sub>					32A <sup>18</sup>	I/0	IO, PD
X2D70	X <sub>2</sub> L6 <sup>4</sup> <sub>out</sub>					32A <sup>19</sup>	I/O	IO, PD
X3D00	$X_2L7_{in}^2$	1A <sup>0</sup>					I/O	IO, PD
X3D01	X <sub>2</sub> L7 <sup>1</sup>	1 B <sup>0</sup>					I/0	IO, PD
X3D02	X <sub>2</sub> L4 <sup>0</sup>		4A <sup>0</sup>	8A <sup>0</sup>	16A <sup>0</sup>	32A <sup>20</sup>	I/0	IO, PD
X3D03	X <sub>2</sub> L4 <sup>0</sup> <sub>out</sub>		4A <sup>1</sup>	8A <sup>1</sup>	16A <sup>1</sup>	32A <sup>21</sup>	I/0	IO, PD
X3D04	X <sub>2</sub> L4 <sup>1</sup> <sub>out</sub>		4B <sup>0</sup>	8A <sup>2</sup>	16A <sup>2</sup>	32A <sup>22</sup>	I/O	IO, PD
X3D05	X <sub>2</sub> L4 <sup>2</sup> <sub>out</sub>		4B <sup>1</sup>	8A <sup>3</sup>	16A <sup>3</sup>	32A <sup>23</sup>	I/0	IO, PD
X3D06	X <sub>2</sub> L4 <sup>3</sup> <sub>out</sub>		4B <sup>2</sup>	8A <sup>4</sup>	16A <sup>4</sup>	32A <sup>24</sup>	I/0	IO, PD
X3D07	X <sub>2</sub> L4 <sup>4</sup> <sub>out</sub>		4B <sup>3</sup>	8A <sup>5</sup>	16A <sup>5</sup>	32A <sup>25</sup>	I/0	IO, PD
X3D08	X <sub>2</sub> L7 <sup>4</sup> <sub>in</sub>		4A <sup>2</sup>	8A <sup>6</sup>	16A <sup>6</sup>	32A <sup>26</sup>	I/O	IO, PD
X3D09	X <sub>2</sub> L7 <sup>3</sup>		4A <sup>3</sup>	8A <sup>7</sup>	16A <sup>7</sup>	32A <sup>27</sup>	I/0	IO, PD
X3D10		1C <sup>0</sup>					I/0	IOT, PD
X3D11		1D <sup>0</sup>					I/0	IOT, PD
X3D12		1E <sup>0</sup>					I/0	IO, PD
X3D13		1F <sup>0</sup>					I/0	IO, PD
X3D14			4C <sup>0</sup>	8B <sup>0</sup>	16A <sup>8</sup>	32A <sup>28</sup>	I/O	IO, PD
X3D15			4C <sup>1</sup>	8B1	16A <sup>9</sup>	32A <sup>29</sup>	I/0	IO, PD
X3D20			4C <sup>2</sup>	8B <sup>6</sup>	16A <sup>14</sup>	32A <sup>30</sup>	I/0	IO, PD
X3D21			4C <sup>3</sup>	8B <sup>7</sup>	16A <sup>15</sup>	32A <sup>31</sup>	I/0	IO, PD
X3D23		1H <sup>0</sup>					I/O	IO, PD
X3D24		11 <sup>0</sup>					I/0	IO, PD
X3D25		1J <sup>0</sup>	_	_	_		I/O	IO, PD
X3D26			4E <sup>0</sup>	8C <sup>0</sup>	16B <sup>0</sup>		I/O	IOT, PD
X3D27			4E <sup>1</sup>	8C <sup>1</sup>	16B <sup>1</sup>		I/O	IOT, PD
X3D28			4F <sup>0</sup>	8C <sup>2</sup>	16B <sup>2</sup>		I/O	IOT, PD
X3D29			4F <sup>1</sup>	8C <sup>3</sup>	16B <sup>3</sup>		I/O	IOT, PD
X3D30			4F <sup>2</sup>	8C <sup>4</sup>	16B <sup>4</sup>		I/O	IOT, PD

## XL232-512-FB374 Datasheet

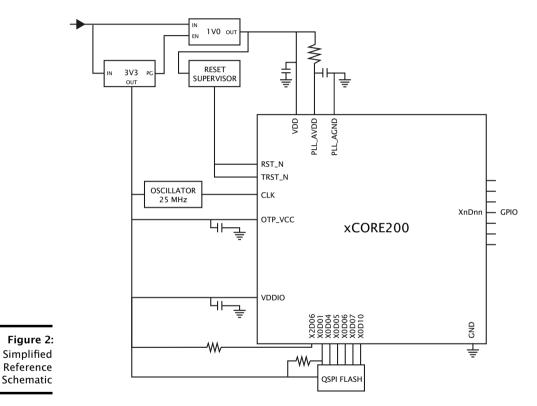
Signal	Function	Туре	Properties
X3D32	4E <sup>2</sup> 8C <sup>6</sup> 16B <sup>6</sup>	I/0	IOT, PD
X3D33	4E <sup>3</sup> 8C <sup>7</sup> 16B <sup>7</sup>	I/0	IOT, PD
X3D40	8D <sup>4</sup> 16B <sup>12</sup>	I/0	IOT, PD
X3D41	8D <sup>5</sup> 16B <sup>13</sup>	I/0	IOT, PD
X3D42	8D <sup>6</sup> 16B <sup>14</sup>	I/0	IOT, PD
X3D43	8D <sup>7</sup> 16B <sup>15</sup>	I/O	IOT, PD

System pins (4)										
Signal	Function	Туре	Properties							
CLK	PLL reference clock	Input	IO, PD, ST							
DEBUG_N	Multi-chip debug	I/O	IO, PU							
MODE0	Boot mode select	Input	PU							
MODE1	Boot mode select	Input	PU							

	usb pins (10)		
Signal	Function	Туре	Properties
USB_2_DM	USB Serial Data Inverted, node 2	I/O	
USB_2_DP	USB Serial Data, node 2	I/O	
USB_2_ID	USB Device ID (OTG) - Reserved, node 2	I/O	
USB_2_RTUNE	USB resistor, node 2	I/O	
USB_2_VBUS	USB Power Detect Pin, node 2	I/O	
USB_DM	USB Serial Data Inverted	I/O	
USB_DP	USB Serial Data	I/O	
USB_ID	USB Device ID (OTG) - Reserved	I/O	
USB_RTUNE	USB resistor	I/O	
USB_VBUS	USB Power Detect Pin	I/O	

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# 5 Example Application Diagram



▶ see Section 11 for details on the power supplies and PCB design

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# 6 Product Overview

The XL232-512-FB374 is a powerful device that consists of four xCORE Tiles, each comprising a flexible logical processing cores with tightly integrated I/O and on-chip memory.

### 6.1 Logical cores

Each tile has 8 active logical cores, which issue instructions down a shared fivestage pipeline. Instructions from the active cores are issued round-robin. If up to five logical cores are active, each core is allocated a fifth of the processing cycles. If more than five logical cores are active, each core is allocated at least 1/n cycles (for *n* cores). Figure 3 shows the guaranteed core performance depending on the number of cores used.

Figure 3: Logical core performance

gure 3:	Speed	MIPS	Frequency		Minim	um MIF	'S per c	ore (fo	r <i>n</i> co	res)	
al core	grade			1	2	3	4	5	6	7	8
mance	20	2000 MIPS	500 MHz	100	100	100	100	100	83	71	63

There is no way that the performance of a logical core can be reduced below these predicted levels (unless *priority threads* are used: in this case the guaranteed minimum performance is computed based on the number of priority threads as defined in the architecture manual). Because cores may be delayed on I/O, however, their unused processing cycles can be taken by other cores. This means that for more than five logical cores, the performance of each core is often higher than the predicted minimum but cannot be guaranteed.

The logical cores are triggered by events instead of interrupts and run to completion. A logical core can be paused to wait for an event.

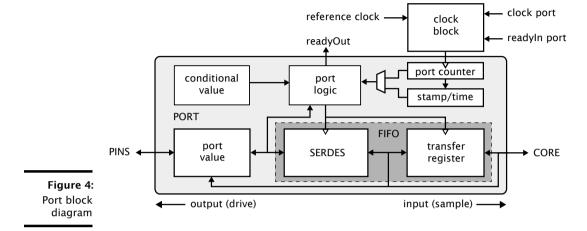
## 6.2 xTIME scheduler

The xTIME scheduler handles the events generated by xCORE Tile resources, such as channel ends, timers and I/O pins. It ensures that all events are serviced and synchronized, without the need for an RTOS. Events that occur at the I/O pins are handled by the Hardware-Response ports and fed directly to the appropriate xCORE Tile. An xCORE Tile can also choose to wait for a specified time to elapse, or for data to become available on a channel.

Tasks do not need to be prioritised as each of them runs on their own logical xCORE. It is possible to share a set of low priority tasks on a single core using cooperative multitasking.

### 6.3 Hardware Response Ports

Hardware Response ports connect an xCORE tile to one or more physical pins and as such define the interface between hardware attached to the XL232-512-FB374, and the software running on it. A combination of 1 bit, 4 bit, 8 bit, 16 bit and 32 bit



ports are available. All pins of a port provide either output or input. Signals in different directions cannot be mapped onto the same port.

The port logic can drive its pins high or low, or it can sample the value on its pins, optionally waiting for a particular condition. Ports are accessed using dedicated instructions that are executed in a single processor cycle. xCORE-200 IO pins can be used as *open collector* outputs, where signals are driven low if a zero is output, but left high impedance if a one is output. This option is set on a per-port basis.

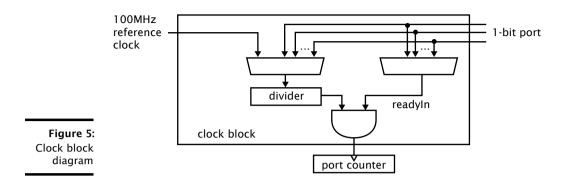
Data is transferred between the pins and core using a FIFO that comprises a SERDES and transfer register, providing options for serialization and buffered data.

Each port has a 16-bit counter that can be used to control the time at which data is transferred between the port value and transfer register. The counter values can be obtained at any time to find out when data was obtained, or used to delay I/O until some time in the future. The port counter value is automatically saved as a timestamp, that can be used to provide precise control of response times.

The ports and xCONNECT links are multiplexed onto the physical pins. If an xConnect Link is enabled, the pins of the underlying ports are disabled. If a port is enabled, it overrules ports with higher widths that share the same pins. The pins on the wider port that are not shared remain available for use when the narrower port is enabled. Ports always operate at their specified width, even if they share pins with another port.

## 6.4 Clock blocks

xCORE devices include a set of programmable clocks called clock blocks that can be used to govern the rate at which ports execute. Each xCORE tile has six clock blocks: the first clock block provides the tile reference clock and runs at a default frequency of 100MHz; the remaining clock blocks can be set to run at different frequencies.



A clock block can use a 1-bit port as its clock source allowing external application clocks to be used to drive the input and output interfaces. xCORE-200 clock blocks optionally divide the clock input from a 1-bit port.

In many cases I/O signals are accompanied by strobing signals. The xCORE ports can input and interpret strobe (known as readyIn and readyOut) signals generated by external sources, and ports can generate strobe signals to accompany output data.

On reset, each port is connected to clock block 0, which runs from the xCORE Tile reference clock.

## 6.5 Channels and Channel Ends

Logical cores communicate using point-to-point connections, formed between two channel ends. A channel-end is a resource on an xCORE tile, that is allocated by the program. Each channel-end has a unique system-wide identifier that comprises a unique number and their tile identifier. Data is transmitted to a channel-end by an output-instruction; and the other side executes an input-instruction. Data can be passed synchronously or asynchronously between the channel ends.

## 6.6 xCONNECT Switch and Links

XMOS devices provide a scalable architecture, where multiple xCORE devices can be connected together to form one system. Each xCORE device has an xCONNECT interconnect that provides a communication infrastructure for all tasks that run on the various xCORE tiles on the system.

The interconnect relies on a collection of switches and XMOS links. Each xCORE device has an on-chip switch that can set up circuits or route data. The switches are connected by xConnect Links. An XMOS link provides a physical connection between two switches. The switch has a routing algorithm that supports many different topologies, including lines, meshes, trees, and hypercubes.

The links operate in either 2 wires per direction or 5 wires per direction mode, depending on the amount of bandwidth required. Circuit switched, streaming

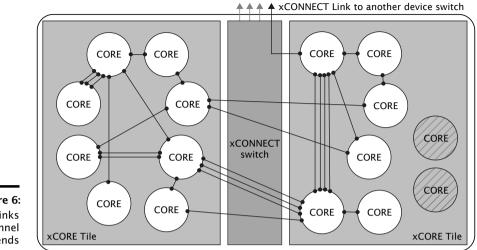


Figure 6: Switch, links and channel ends

and packet switched data can both be supported efficiently. Streams provide the fastest possible data rates between xCORE Tiles (up to 250 MBit/s), but each stream requires a single link to be reserved between switches on two tiles. All packet communications can be multiplexed onto a single link.

Information on the supported routing topologies that can be used to connect multiple devices together can be found in the XS1-L Link Performance and Design Guide, X2999.

# 7 PLL

The PLL creates a high-speed clock that is used for the switch, tile, and reference clock. The PLL multiplication value is selected through the two MODE pins, and can be changed by software to speed up the tile or use less power. The MODE pins are set as shown in Figure 7:

Figure 7: PLL multiplier values and MODE pins

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	Oscillator	MC	DDE	Tile Boot	PLL Ratio	PLL	setting	gs	
	Frequency	1	0	Frequency		OD	F	R	
e 7:	3.25-10 MHz	0	0	130-400 MHz	40	1	159	0	
lier	9-25 MHz	1	1	144-400 MHz	16	1	63	0	
and	25-50 MHz	1	0	167-400 MHz	8	1	31	0	
oins	50-100 MHz	0	1	196-400 MHz	4	1	15	0	

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Figure 7 also lists the values of OD, F and R, which are the registers that define the ratio of the tile frequency to the oscillator frequency:

$$F_{core} = F_{osc} \times \frac{F+1}{2} \times \frac{1}{R+1} \times \frac{1}{OD+1}$$

*OD*, *F* and *R* must be chosen so that  $0 \le R \le 63$ ,  $0 \le F \le 4095$ ,  $0 \le OD \le 7$ , and  $260MHz \le F_{osc} \times \frac{F+1}{2} \times \frac{1}{R+1} \le 1.3GHz$ . The *OD*, *F*, and *R* values can be modified by writing to the digital node PLL configuration register.

The MODE pins must be held at a static value during and after deassertion of the system reset.

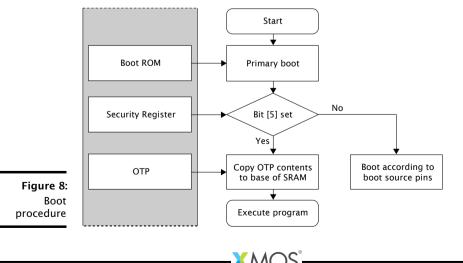
If a different tile frequency is required (eg, 500 MHz), then the PLL must be reprogrammed after boot to provide the required tile frequency. The XMOS tools perform this operation by default. Further details on configuring the clock can be found in the xCORE-200 Clock Frequency Control document.

## 8 Boot Procedure

The device is kept in reset by driving RST\_N low. When in reset, all GPIO pins have a pull-down enabled. When the device is taken out of reset by releasing RST\_N the processor starts its internal reset process. After 15-150  $\mu$ s (depending on the input clock) the processor boots.

Pin X2D06 must be pulled high with an external pull-up whilst the chip comes out of reset, to ensure that tile 2 will boot from link. X2D04, X2D05, and X2D07 should be kept low whilst the chip comes out of reset.

The xCORE Tile boot procedure is illustrated in Figure 8. If bit 5 of the security register (*see* §9.1) is set, the device boots from OTP. To get a high value, a 3K3 pull-up resistor should be strapped onto the pin. To assure a low value, a pull-down resistor is required if other external devices are connected to this port.



	X0D06	X0D05	X0D04	Tile 0 boot	Tile 1 boot	Enabled links
	0	0	0	QSPI master	Channel end 0	None
	0	0	1	SPI master	Channel end 0	None
Figure 9:	0	1	0	SPI slave	Channel end 0	None
Boot source	0	1	1	SPI slave	SPI slave	None
pins	1	0	0	Channel end 0	Channel end 0	XL0 (2w)

The boot image has the following format:

- ► A 32-bit program size *s* in words.
- Program consisting of  $s \times 4$  bytes.
- A 32-bit CRC, or the value 0x0D15AB1E to indicate that no CRC check should be performed.

The program size and CRC are stored least significant byte first. The program is loaded into the lowest memory address of RAM, and the program is started from that address. The CRC is calculated over the byte stream represented by the program size and the program itself. The polynomial used is 0xEDB88320 (IEEE 802.3); the CRC register is initialized with 0xFFFFFFFF and the residue is inverted to produce the CRC.

### 8.1 Boot from QSPI master

If set to boot from QSPI master, the processor enables the six pins specified in Figure 10, and drives the SPI clock at 50 MHz (assuming a 400 MHz core clock). A READ command is issued with a 24-bit address 0x000000. The clock polarity and phase are 0 / 0.

	Pin	Signal	Description
	X0D01	SS	Slave Select
Figure 10:	X0D04X0D07	SPIO	Data
QSPI pins	X0D10	SCLK	Clock

The xCORE Tile expects each byte to be transferred with the *least-significant nibble first*. Programmers who write bytes into an QSPI interface using the most significant nibble first may have to reverse the nibbles in each byte of the image stored in the QSPI device.

The pins used for QSPI boot are hardcoded in the boot ROM and cannot be changed. If required, an QSPI boot program can be burned into OTP that uses different pins.

### 8.2 Boot from SPI master

If set to boot from SPI master, the processor enables the four pins specified in Figure 11, and drives the SPI clock at 2.5 MHz (assuming a 400 MHz core clock). A

READ command is issued with a 24-bit address 0x000000. The clock polarity and phase are 0 / 0.

	Pin	Signal	Description
	X0D00	MISO	Master In Slave Out (Data)
Figure 11:	X0D01	SS	Slave Select
SPI master	X0D10	SCLK	Clock
pins	X0D11	MOSI	Master Out Slave In (Data)

The xCORE Tile expects each byte to be transferred with the *least-significant bit first*. Programmers who write bytes into an SPI interface using the most significant bit first may have to reverse the bits in each byte of the image stored in the SPI device.

If a large boot image is to be read in, it is faster to first load a small boot-loader that reads the large image using a faster SPI clock, for example 50 MHz or as fast as the flash device supports.

The pins used for SPI boot are hardcoded in the boot ROM and cannot be changed. If required, an SPI boot program can be burned into OTP that uses different pins.

### 8.3 Boot from SPI slave

If set to boot from SPI slave, the processor enables the three pins specified in Figure 12 and expects a boot image to be clocked in. The supported clock polarity and phase are 0/0 and 1/1.

	Pin	Signal	Description
	X0D00	SS	Slave Select
Figure 12:	X0D10	SCLK	Clock
SPI slave pins	X0D11	MOSI	Master Out Slave In (Data)

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The xCORE Tile expects each byte to be transferred with the *least-significant bit first*. The pins used for SPI boot are hardcoded in the boot ROM and cannot be changed. If required, an SPI boot program can be burned into OTP that uses different pins.

### 8.4 Boot from xConnect Link

If set to boot from an xConnect Link, the processor enables its link(s) around 2 us after the boot process starts. Enabling the Link switches off the pull-down resistors on the link, drives all the TX wires low (the initial state for the Link), and monitors the RX pins for boot-traffic; they must be low at this stage. If the internal pull-down is too weak to drain any residual charge, external pull-downs of 10K may be required on those pins.

The boot-rom on the core will then:

1. Allocate channel-end 0.

- 2. Input a word on channel-end 0. It will use this word as a channel to acknowledge the boot. Provide the null-channel-end 0x0000FF02 if no acknowledgment is required.
- 3. Input the boot image specified above, including the CRC.
- 4. Input an END control token.
- 5. Output an END control token to the channel-end received in step 2.
- 6. Free channel-end 0.
- 7. Jump to the loaded code.

### 8.5 Boot from OTP

If an xCORE tile is set to use secure boot (see Figure 8), the boot image is read from address 0 of the OTP memory in the tile's security module.

This feature can be used to implement a secure bootloader which loads an encrypted image from external flash, decrypts and CRC checks it with the processor, and discontinues the boot process if the decryption or CRC check fails. XMOS provides a default secure bootloader that can be written to the OTP along with secret decryption keys.

Each tile has its own individual OTP memory, and hence some tiles can be booted from OTP while others are booted from SPI or the channel interface. This enables systems to be partially programmed, dedicating one or more tiles to perform a particular function, leaving the other tiles user-programmable.

### 8.6 Security register

The security register enables security features on the xCORE tile. The features shown in Figure 13 provide a strong level of protection and are sufficient for providing strong IP security.

## 9 Memory

### 9.1 OTP

Each xCORE Tile integrates 8 KB one-time programmable (OTP) memory along with a security register that configures system wide security features. The OTP holds data in four sectors each containing 512 rows of 32 bits which can be used to implement secure bootloaders and store encryption keys. Data for the security register is loaded from the OTP on power up. All additional data in OTP is copied from the OTP to SRAM and executed first on the processor.

The OTP memory is programmed using three special I/O ports: the OTP address port is a 16-bit port with resource ID 0x100200, the OTP data is written via a 32-bit

Feature	Bit	Description
Disable JTAG	0	The JTAG interface is disabled, making it impossible for the tile state or memory content to be accessed via the JTAG interface.
Disable Link access	1	Other tiles are forbidden access to the processor state via the system switch. Disabling both JTAG and Link access transforms an xCORE Tile into a "secure island" with other tiles free for non-secure user application code.
Secure Boot	5	The xCORE Tile is forced to boot from address 0 of the OTP, allowing the xCORE Tile boot ROM to be bypassed ( <i>see</i> §8).
Redundant rows	7	Enables redundant rows in OTP.
Sector Lock 0	8	Disable programming of OTP sector 0.
Sector Lock 1	9	Disable programming of OTP sector 1.
Sector Lock 2	10	Disable programming of OTP sector 2.
Sector Lock 3	11	Disable programming of OTP sector 3.
OTP Master Lock	12	Disable OTP programming completely: disables up dates to all sectors and security register.
Disable JTAG-OTP	13	Disable all (read & write) access from the JTAG inter face to this OTP.
Disable Global Debug	14	Disables access to the DEBUG_N pin.
	2115	General purpose software accessable security registe available to end-users.
	3122	General purpose user programmable JTAG UserIE code extension.

Figure 13: Security register features

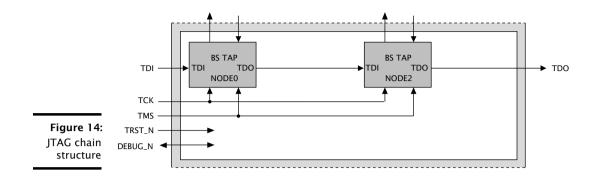
port with resource ID 0x200100, and the OTP control is on a 16-bit port with ID 0x100300. Programming is performed through libotp and xburn.

## 9.2 SRAM

Each xCORE Tile integrates a single 128KBSRAM bank for both instructions and data. All internal memory is 32 bits wide, and instructions are either 16-bit or 32-bit. Byte (8-bit), half-word (16-bit) or word (32-bit) accesses are supported and are executed within one tile clock cycle. There is no dedicated external memory interface, although data memory can be expanded through appropriate use of the ports.

# 10 JTAG

The JTAG module can be used for loading programs, boundary scan testing, incircuit source-level debugging and programming the OTP memory.



The JTAG chain structure is illustrated in Figure 14. It comprises two 1149.1 compliant TAPs that can be used for boundary scan of the I/O pins. Each tap has a 4-bit IR and 32-bit DR. It also provides access to a chip TAP that in turn can access the xCORE Tile for loading code and debugging.

The TRST\_N pin must be asserted low during and after power up for 100 ns. If JTAG is not required, the TRST\_N pin can be tied to ground to hold the JTAG module in reset.

The DEBUG\_N pin is used to synchronize the debugging of multiple xCORE Tiles. This pin can operate in both output and input mode. In output mode and when configured to do so, DEBUG\_N is driven low by the device when the processor hits a debug break point. Prior to this point the pin will be tri-stated. In input mode and when configured to do so, driving this pin low will put the xCORE Tile into debug mode. Software can set the behavior of the xCORE Tile based on this pin. This pin should have an external pull up of 4K7-47K  $\Omega$  or left not connected in single core applications.

The JTAG device identification register can be read by using the IDCODE instruction. Its contents are specified in Figure 15.

Figure 15: IDCODE return value

Bit	31											D	evice	e Ide	ntifi	catio	on R	egist	er											E	Bit0
	Ver	sion								Pa	rt N	umb	er									I	Man	ufac	ture	r Ide	ntity	1			1
0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	1	0	1	1	0	0	0	1	1	0	0	1	1
		0			(	)			. (	) )			(	)				5			. 6	5			3	3			3	3	

The JTAG usercode register can be read by using the USERCODE instruction. Its contents are specified in Figure 16. The OTP User ID field is read from bits [22:31] of the security register on xCORE Tile 0, *see* §9.1 (all zero on unprogrammed devices).

Figure 16: USERCODE return value

	Bit	31													User	code	e Reg	giste	r												В	it0
				0	ΟΤΡ Ι	Jser	ID					Unu	ised									Silio	on I	Revis	sion						-	
Ī	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Ī			0				0			. (	0				2				8			(	)			(	)			(	)	

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# 11 Board Integration

The device has the following power supply pins:

- VDD pins for the xCORE Tile, including USB\_VDD and USB\_2\_VDD pins that power the USB PHY
- VDDIO pins for the I/O lines
- PLL\_AVDD pins for the PLL
- ▶ OTP\_VCC pins for the OTP
- ▶ USB\_VDD33 and USB\_2\_VDD33 pins for the analogue supply to the USB-PHY

Several pins of each type are provided to minimize the effect of inductance within the package, all of which must be connected. The power supplies must be brought up monotonically and input voltages must not exceed specification at any time.

The VDD supply must ramp from 0V to its final value within 10 ms to ensure correct startup.

The VDDIO and OTP\_VCC supply must ramp to its final value before VDD reaches 0.4 V.

The PLL\_AVDD supply should be separated from the other noisier supplies on the board. The PLL requires a very clean power supply, and a low pass filter (for example, a  $2.2 \Omega$  resistor and 100 nF multi-layer ceramic capacitor) is recommended on this pin.

The following ground pins are provided:

- PLL\_AGND for PLL\_AVDD
- ► GND for all other supplies

All ground pins must be connected directly to the board ground.

The VDD and VDDIO supplies should be decoupled close to the chip by several 100 nF low inductance multi-layer ceramic capacitors between the supplies and GND (for example, 100nF 0402 for every other supply pin). The ground side of the decoupling capacitors should have as short a path back to the GND pins as possible. A bulk decoupling capacitor of at least 10 uF should be placed on each of these supplies.

RST\_N is an active-low asynchronous-assertion global reset signal. Following a reset, the PLL re-establishes lock after which the device boots up according to the boot mode (*see* §8). RST\_N and must be asserted low during and after power up for 100 ns.

### 11.1 Land patterns and solder stencils

The package is a 374 ball Fine Ball Grid Array (FBGA) on a 0.8 mm pitch.



The land patterns and solder stencils will depend on the PCB manufacturing process. We recommend you design them with using the IPC specifications *"Generic Requirements for Surface Mount Design and Land Pattern Standards"* IPC-7351B. This standard aims to achieve desired targets of heel, toe and side fillets for solder-joints. The mechanical drawings in Section 13 specify the dimensions and tolerances.

### 11.2 Ground and Thermal Vias

Vias next to each ground ball into the ground plane of the PCB are recommended for a low inductance ground connection and good thermal performance.

### 11.3 Moisture Sensitivity

XMOS devices are, like all semiconductor devices, susceptible to moisture absorption. When removed from the sealed packaging, the devices slowly absorb moisture from the surrounding environment. If the level of moisture present in the device is too high during reflow, damage can occur due to the increased internal vapour pressure of moisture. Example damage can include bond wire damage, die lifting, internal or external package cracks and/or delamination.

All XMOS devices are Moisture Sensitivity Level (MSL) 3 - devices have a shelf life of 168 hours between removal from the packaging and reflow, provided they are stored below 30C and 60% RH. If devices have exceeded these values or an included moisture indicator card shows excessive levels of moisture, then the parts should be baked as appropriate before use. This is based on information from *Joint IPC/JEDEC Standard For Moisture/Reflow Sensitivity Classification For Nonhermetic Solid State Surface-Mount Devices* J-STD-020 Revision D.

# 12 Electrical Characteristics

### 12.1 Absolute Maximum Ratings

Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

Symbol	Parameter	MIN	MAX	UNITS	Notes
VDD	Tile DC supply voltage	-0.2	1.1	V	
PLL_AVDD	PLL analog supply	-0.2	1.1	V	
VDDIO	I/O supply voltage	-0.3	3.75	V	
OTP_VCC	OTP supply voltage	-0.3	3.75	V	
Тј	Junction temperature		125	°C	
Tstg	Storage temperature	-65	150	°C	
V(Vin)	Voltage applied to any IO pin	-0.3	3.75	V	
I(XxDxx)	GPIO current	-30	30	mA	
I(VDDIO)	Current for VDDIO domain		2064	mA	A, B, C
I(VDDIOT)	Current for VDDIOT domain		98	mA	A, C

Figure 17: Absolute maximum ratings

A Exceeding these current limits will result in premature aging and reduced lifetime.

B This current consumption must be evenly distributed over all VDDIO pins.

C All main power (VDD, VDDIO) and ground (VSS) pins must always be connected to the external power supply, in the permitted range.

Symbol	Parameter	MIN	ТҮР	MAX	UNITS	Notes
VDD	Tile DC supply voltage	0.95	1.00	1.05	V	
VDDIO	I/O supply voltage	2.30	3.30	3.60	V	
VDDIOT 3v3	I/O supply voltage	3.135	3.30	3.465	V	
VDDIOT 2v5	I/O supply voltage	2.375	2.50	2.625	V	
USB_VDD	USB tile DC supply voltage	0.95	1.00	1.05	V	
VDD33	Peripheral supply	3.135	3.30	3.465	V	
PLL_AVDD	PLL analog supply	0.95	1.00	1.05	V	
Cl	xCORE Tile I/O load capacitance			25	pF	
Та	Ambient operating temperature (Commercial)	0		70	°C	
	Ambient operating temperature (Industrial)	-40		85	°C	
Тј	Junction temperature			125	°C	

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## 12.2 Operating Conditions

Figure 18: Operating conditions

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
V(IH)	Input high voltage	2.00		3.60	V	A
V(IL)	Input low voltage	-0.30		0.70	V	A
V(OH)	Output high voltage	2.20			V	B, C
V(OL)	Output low voltage			0.40	V	B, C
I(PU)	Internal pull-up current (Vin=0V)	-100			μA	D
I(PD)	Internal pull-down current (Vin=3.3V)			100	μA	D
I(LC)	Input leakage current	-10		10	μA	

### 12.3 DC Characteristics, VDDIO=3V3

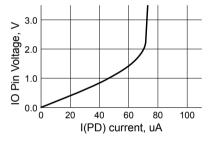
Figure 19: DC characteristics

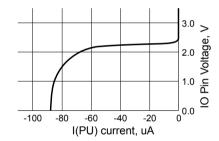
A All pins except power supply pins.

B Pins X1D40, X1D41, X1D42, X1D43, X1D26, X1D27, X3D40, X3D41, X3D42, X3D43, X3D26, and X3D27 are nominal 8 mA drivers, the remainder of the general-purpose I/Os are 4 mA.

- C Measured with 4 mA drivers sourcing 4 mA, 8 mA drivers sourcing 8 mA.
- D Used to guarantee logic state for an I/O when high impedance. The internal pull-ups/pull-downs should not be used to pull external circuitry. In order to pull the pin to the opposite state, a 4K7 resistor is recommended to overome the internal pull current.

Figure 20: Typical internal pull-down and pull-up currents





## 12.4 ESD Stress Voltage

Figure 21:	Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
ESD stress	HBM	Human body model	-2.00		2.00	KV	
voltage	CDM	Charged Device Model	-500		500	V	

## 12.5 Reset Timing

5:	Symbol	Parameters	MIN	TYP	MAX	UNITS	Notes
Figure 22:	T(RST)	Reset pulse width	5			μs	
Reset timing	T(INIT)	Initialization time			150	μs	А

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A Shows the time taken to start booting after RST\_N has gone high.

### 12.6 Power Consumption

Symbol	Parameter	MIN	ТҮР	MAX	UNITS	Notes
I(DDCQ)	Quiescent VDD current		90		mA	A, B, C
PD	Tile power dissipation		325		µW/MIPS	A, D, E, F
IDD	Active VDD current		1140	1400	mA	A, G
I(ADDPLL)	PLL_AVDD current		10	14	mA	Н
I(VDD33)	VDD33 current		53.4		mA	I
I(USB_VDD)	USB_VDD current		16.6		mA	J

Figure 23: xCORE Tile currents

A Use for budgetary purposes only.

- B Assumes typical tile and I/O voltages with no switching activity.
- C Includes PLL current.
- D Assumes typical tile and I/O voltages with nominal switching activity.
- E Assumes 1 MHz = 1 MIPS.
- F PD(TYP) value is the usage power consumption under typical operating conditions.
- G Measurement conditions: VDD = 1.0 V, VDDIO = 3.3 V, 25 °C, 500 MHz, average device resource usage.
- H PLL\_AVDD = 1.0 V
- I HS mode transmitting while driving all 0's data (constant JKJK on DP/DM). Loading of 10 pF. Transfers do not include any interpacket delay.
- J HS receive mode; no traffic.



The tile power consumption of the device is highly application dependent and should be used for budgetary purposes only.

More detailed power analysis can be found in the XS1-L Power Consumption document,

### 12.7 Clock

Figure 24: Clock

Symbol	Parameter	MIN	ТҮР	MAX	UNITS	Notes
f	Frequency	3.25	24	100	MHz	
SR	Slew rate	0.10			V/ns	
TJ(LT)	Long term jitter (pk-pk)			2	%	А
f(MAX)	Processor clock frequency			500	MHz	В

A Percentage of CLK period.

B Assumes typical tile and I/O voltages with nominal activity.

Further details can be found in the XS1-L Clock Frequency Control document,

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X010435,

	Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
	T(XOVALID)	Input data valid window	8			ns	
Figure 25:	T(XOINVALID)	Output data invalid window	9			ns	
I/O AC char- acteristics	T(XIFMAX)	Rate at which data can be sampled with respect to an external clock			60	MHz	

12.8	xCORE Tile	e I/O AC	Characteristics
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The input valid window parameter relates to the capability of the device to capture data input to the chip with respect to an external clock source. It is calculated as the sum of the input setup time and input hold time with respect to the external clock as measured at the pins. The output invalid window specifies the time for which an output is invalid with respect to the external clock. Note that these parameters are specified as a window rather than absolute numbers since the device provides functionality to delay the incoming clock with respect to the incoming data.

Information on interfacing to high-speed synchronous interfaces can be found in the Port I/O Timing document, X5821.

### 12.9 xConnect Link Performance

	Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
	B(2blinkP)	2b link bandwidth (packetized)			87	MBit/s	А, В
Figure 26:	B(5blinkP)	5b link bandwidth (packetized)			217	MBit/s	А, В
Link	B(2blinkS)	2b link bandwidth (streaming)			100	MBit/s	В
performance	B(5blinkS)	5b link bandwidth (streaming)			250	MBit/s	В

A Assumes 32-byte packet in 3-byte header mode. Actual performance depends on size of the header and payload.

B 7.5 ns symbol time.

The asynchronous nature of links means that the relative phasing of CLK clocks is not important in a multi-clock system, providing each meets the required stability criteria.

12.10 JTAG Timing	12.1	0	JTAG	Timing
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	Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
	f(TCK_D)	TCK frequency (debug)			18	MHz	
	f(TCK_B)	TCK frequency (boundary scan)			10	MHz	
-	T(SETUP)	TDO to TCK setup time	5			ns	А
<b>7</b> :	T(HOLD)	TDO to TCK hold time	5			ns	А
9	T(DELAY)	TCK to output delay			15	ns	В

Figure 27: JTAG timing

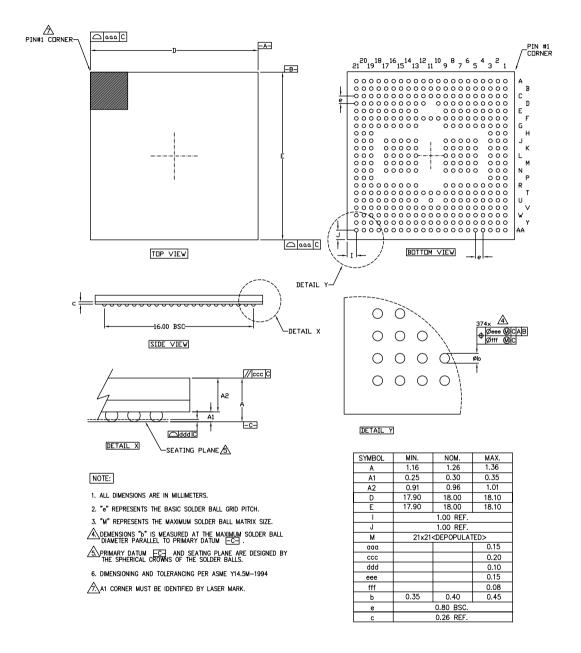
A Timing applies to TMS and TDI inputs.

B Timing applies to TDO output from negative edge of TCK.

All JTAG operations are synchronous to TCK apart from the global asynchronous reset TRST\_N.

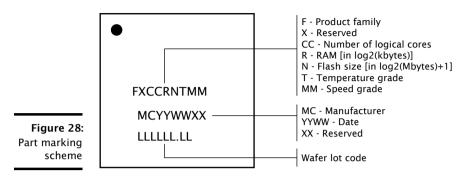
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# 13 Package Information



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# 13.1 Part Marking



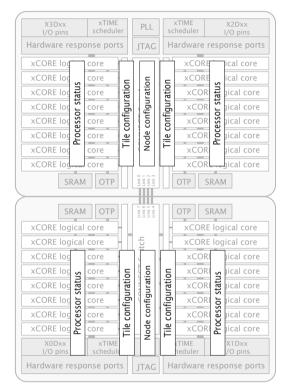
# 14 Ordering Information

Figure 29:	Product Code	Marking	Qualification	Speed Grade
Orderable	XL232-512-FB374-C40	L13290C40	Commercial	2000 MIPS
part numbers	XL232-512-FB374-I40	L13290C40	Industrial	2000 MIPS

# Appendices

# A Configuration of the XL232-512-FB374

The device is configured through banks of registers, as shown in Figure 30.



### Figure 30: Registers

The following communication sequences specify how to access those registers. Any messages transmitted contain the most significant 24 bits of the channel-end to which a response is to be sent. This comprises the node-identifier and the channel number within the node. if no response is required on a write operation, supply 24-bits with the last 8-bits set, which suppresses the reply message. Any multi-byte data is sent most significant byte first.

# A.1 Accessing a processor status register

The processor status registers are accessed directly from the processor instruction set. The instructions GETPS and SETPS read and write a word. The register number should be translated into a processor-status resource identifier by shifting the register number left 8 places, and ORing it with 0x0B. Alternatively, the functions getps(reg) and setps(reg,value) can be used from XC.



### A.2 Accessing an xCORE Tile configuration register

xCORE Tile configuration registers can be accessed through the interconnect using the functions write\_tile\_config\_reg(tileref, ...) and read\_tile\_config\_reg(tile  $\rightarrow$  ref, ...), where tileref is the name of the xCORE Tile, e.g. tile[1]. These functions implement the protocols described below.

Instead of using the functions above, a channel-end can be allocated to communicate with the xCORE tile configuration registers. The destination of the channel-end should be set to 0xnnnnC20C where nnnnn is the tile-identifier.

A write message comprises the following:

control-token	24-bit response	16-bit	32-bit	control-token
192	channel-end identifier	register number	data	1

The response to a write message comprises either control tokens 3 and 1 (for success), or control tokens 4 and 1 (for failure).

A read message comprises the following:

control-token	24-bit response	16-bit	control-token
193	channel-end identifier	register number	1

The response to the read message comprises either control token 3, 32-bit of data, and control-token 1 (for success), or control tokens 4 and 1 (for failure).

### A.3 Accessing node configuration

Node configuration registers can be accessed through the interconnect using the functions write\_node\_config\_reg(device, ...) and read\_node\_config\_reg(device, ...), where device is the name of the node. These functions implement the protocols described below.

Instead of using the functions above, a channel-end can be allocated to communicate with the node configuration registers. The destination of the channel-end should be set to 0xnnnnC30C where nnnn is the node-identifier.

A write message comprises the following:

control-token	24-bit response	16-bit	32-bit	control-token
192	channel-end identifier	register number	data	1

The response to a write message comprises either control tokens 3 and 1 (for success), or control tokens 4 and 1 (for failure).

A read message comprises the following:

control-token	24-bit response	16-bit	control-token
193	channel-end identifier	register number	1

The response to a read message comprises either control token 3, 32-bit of data, and control-token 1 (for success), or control tokens 4 and 1 (for failure).

# **B** Processor Status Configuration

The processor status control registers can be accessed directly by the processor using processor status reads and writes (use getps(reg) and setps(reg,value) for reads and writes).

Number	Perm	Description
0x00	RW	RAM base address
0x01	RW	Vector base address
0x02	RW	xCORE Tile control
0x03	RO	xCORE Tile boot status
0x05	RW	Security configuration
0x06	RW	Ring Oscillator Control
0x07	RO	Ring Oscillator Value
0x08	RO	Ring Oscillator Value
0x09	RO	Ring Oscillator Value
0x0A	RO	Ring Oscillator Value
0x0C	RO	RAM size
0x10	DRW	Debug SSR
0x11	DRW	Debug SPC
0x12	DRW	Debug SSP
0x13	DRW	DGETREG operand 1
0x14	DRW	DGETREG operand 2
0x15	DRW	Debug interrupt type
0x16	DRW	Debug interrupt data
0x18	DRW	Debug core control
0x20 0x27	DRW	Debug scratch
0x30 0x33	DRW	Instruction breakpoint address
0x40 0x43	DRW	Instruction breakpoint control
0x50 0x53	DRW	Data watchpoint address 1
0x60 0x63	DRW	Data watchpoint address 2
0x70 0x73	DRW	Data breakpoint control register
0x80 0x83	DRW	Resources breakpoint mask
0x90 0x93	DRW	Resources breakpoint value
0x9C 0x9F	DRW	Resources breakpoint control register

Figure 31:

Summary

X010435,

### B.1 RAM base address: 0x00

This register contains the base address of the RAM. It is initialized to 0x00040000.

**0x00:** RAM base address

00:	Bits	Perm	Init	Description
ase	31:2	RW		Most significant 16 bits of all addresses.
ess	1:0	RO	-	Reserved

### B.2 Vector base address: 0x01

Base address of event vectors in each resource. On an interrupt or event, the 16 most significant bits of the destination address are provided by this register; the least significant 16 bits come from the event vector.

0x01: Vector base address

	Bits	Perm	Init	Description
•	31:18	RW		The event and interrupt vectors.
	17:0	RO	-	Reserved

### B.3 xCORE Tile control: 0x02

Register to control features in the xCORE tile

Bits	Perm	Init	Description
31:26	RO	-	Reserved
25:18	RW	0	RGMII TX data delay value (in PLL output cycle increments)
17:9	RW	0	RGMII TX clock divider value. TX clk rises when counter (clocked by PLL output) reaches this value and falls when counter reaches (value»1). Value programmed into this field should be actual divide value required minus 1
8	RW	0	Enable RGMII interface periph ports
7:6	RO	-	Reserved
5	RW	0	Select the dynamic mode (1) for the clock divider when the clock divider is enabled. In dynamic mode the clock divider is only activated when all active threads are paused. In static mode the clock divider is always enabled.
4	RW	0	Enable the clock divider. This divides the output of the PLL to facilitate one of the low power modes.
3:0	RO	-	Reserved

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0x02: xCORE Tile control



### B.4 xCORE Tile boot status: 0x03

This read-only register describes the boot status of the xCORE tile.

Bits	Perm	Init	Description
31:24	RO	-	Reserved
23:16	RO		Processor number.
15:9	RO	-	Reserved
8	RO		Overwrite BOOT_MODE.
7:6	RO	-	Reserved
5	RO		Indicates if core1 has been powered off
4	RO		Cause the ROM to not poll the OTP for correct read levels
3	RO		Boot ROM boots from RAM
2	RO		Boot ROM boots from JTAG
1:0	RO		The boot PLL mode pin value.

0x03: xCORE Tile boot status

## **B.5** Security configuration: 0x05

Copy of the security register as read from OTP.

Bits	Perm	Init	Description
31	RW		Disables write permission on this register
30:15	RO	-	Reserved
14	RW		Disable access to XCore's global debug
13	RO	-	Reserved
12	RW		lock all OTP sectors
11:8	RW		lock bit for each OTP sector
7	RW		Enable OTP reduanacy
6	RO	-	Reserved
5	RW		Override boot mode and read boot image from OTP
4	RW		Disable JTAG access to the PLL/BOOT configuration registers
3:1	RO	-	Reserved
0	RW		Disable access to XCore's JTAG debug TAP

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**0x05:** Security configuration

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### B.6 Ring Oscillator Control: 0x06

There are four free-running oscillators that clock four counters. The oscillators can be started and stopped using this register. The counters should only be read when the ring oscillator has been stopped for at least 10 core clock cycles (this can be achieved by inserting two nop instructions between the SETPS and GETPS). The counter values can be read using four subsequent registers. The ring oscillators are asynchronous to the xCORE tile clock and can be used as a source of random bits.

**0x06:** Ring Oscillator Control

_	Bits	Perm	Init	Description
6:	31:2	RO	-	Reserved
g or	1	RW	0	Core ring oscillator enable.
ol	0	RW	0	Peripheral ring oscillator enable.

### B.7 Ring Oscillator Value: 0x07

This register contains the current count of the xCORE Tile Cell ring oscillator. This value is not reset on a system reset.

**0x07** Ring Oscillator Value

: <b>07:</b> ing	Bits	Perm	Init	Description
tor	31:16	RO	-	Reserved
lue	15:0	RO	0	Ring oscillator Counter data.

### B.8 Ring Oscillator Value: 0x08

This register contains the current count of the xCORE Tile Wire ring oscillator. This value is not reset on a system reset.

**0x08:** Ring Oscillator Value

8: a	Bits	Perm	Init	Description
g or	31:16	RO	-	Reserved
e	15:0	RO	0	Ring oscillator Counter data.

### B.9 Ring Oscillator Value: 0x09

This register contains the current count of the Peripheral Cell ring oscillator. This value is not reset on a system reset.

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<b>0x09:</b> Ring	Bits	Perm	Init	Description
Oscillator	31:16	RO	-	Reserved
Value	15:0	RO	0	Ring oscillator Counter data.

### B.10 Ring Oscillator Value: 0x0A

This register contains the current count of the Peripheral Wire ring oscillator. This value is not reset on a system reset.

**0x0A** Rin<u>c</u> Oscillato Value

<b>(0A:</b> Ring	Bits	Perm	Init	Description
ator	31:16	RO	-	Reserved
alue	15:0	RO	0	Ring oscillator Counter data.

### B.11 RAM size: 0x0C

The size of the RAM in bytes

**0x0C:** RAM size

-	Bits	Perm	Init	Description
:	31:2	RO		Most significant 16 bits of all addresses.
į	1:0	RO	-	Reserved

### B.12 Debug SSR: 0x10

This register contains the value of the SSR register when the debugger was called.

Bits	Perm	Init	Description
31:11	RO	-	Reserved
10	DRW		Address space indentifier
9	DRW		Determines the issue mode (DI bit) upon Kernel Entry after Exception or Interrupt.
8	RO		Determines the issue mode (DI bit).
7	DRW		When 1 the thread is in fast mode and will continually issue.
6	DRW		When 1 the thread is paused waiting for events, a lock or another resource.
5	RO	-	Reserved
4	DRW		1 when in kernel mode.
3	DRW		1 when in an interrupt handler.
2	DRW		1 when in an event enabling sequence.
1	DRW		When 1 interrupts are enabled for the thread.
0	DRW		When 1 events are enabled for the thread.

0x10: Debug SSR

### B.13 Debug SPC: 0x11

This register contains the value of the SPC register when the debugger was called.

0x11:	Bits	Perm	Init	Description
Debug SPC	31:0	DRW		Value.

### B.14 Debug SSP: 0x12

This register contains the value of the SSP register when the debugger was called.

<b>0x12:</b> Debug SSP	Bits	Perm	Init	Description
	31:0	DRW		Value.

### B.15 DGETREG operand 1: 0x13

The resource ID of the logical core whose state is to be read.

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0x13:	Bits	Perm	Init	Description
DGETREG	31:8	RO	-	Reserved
operand 1	7:0	DRW		Thread number to be read

### B.16 DGETREG operand 2: 0x14

Register number to be read by DGETREG

**0x14:** DGETREG operand 2

-  :	Bits	Perm	Init	Description
	31:5	RO	-	Reserved
2	4:0	DRW		Register number to be read

### B.17 Debug interrupt type: 0x15

Register that specifies what activated the debug interrupt.

Bits	Perm	Init	Description
31:18	RO	-	Reserved
17:16	DRW		Number of the hardware breakpoint/watchpoint which caused the interrupt (always 0 for =HOST= and =DCALL=). If multiple breakpoints/watchpoints trigger at once, the lowest number is taken.
15:8	DRW		Number of thread which caused the debug interrupt (always 0 in the case of =HOST=).
7:3	RO	-	Reserved
2:0	DRW	0	Indicates the cause of the debug interrupt 1: Host initiated a debug interrupt through JTAG 2: Program executed a DCALL instruction 3: Instruction breakpoint 4: Data watch point 5: Resource watch point

**0x15:** Debug interrupt type

### B.18 Debug interrupt data: 0x16

On a data watchpoint, this register contains the effective address of the memory operation that triggered the debugger. On a resource watchpoint, it countains the resource identifier.

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0x16:				
Debug	Bits	Perm	Init	Description
interrupt data	31:0	DRW		Value.

#### B.19 Debug core control: 0x18

This register enables the debugger to temporarily disable logical cores. When returning from the debug interrupts, the cores set in this register will not execute. This enables single stepping to be implemented.

0x18: Debug core control

Bits	Perm	Init	Description
31:8	RO	-	Reserved
7:0	DRW		1-hot vector defining which threads are stopped when not in debug mode. Every bit which is set prevents the respective thread from running.

#### B.20 Debug scratch: 0x20 .. 0x27

A set of registers used by the debug ROM to communicate with an external debugger, for example over JTAG. This is the same set of registers as the Debug Scratch registers in the xCORE tile configuration.

0x20 .. 0x27: Debug scratch

0x27: ebug	Bits	Perm	Init	Description
ratch	31:0	DRW		Value.

#### B.21 Instruction breakpoint address: 0x30 .. 0x33

This register contains the address of the instruction breakpoint. If the PC matches this address, then a debug interrupt will be taken. There are four instruction breakpoints that are controlled individually.

0x30 .. 0x33: Instruction breakpoint address

ction point	Bits	Perm	Init	Description
dress	31:0	DRW		Value.

### B.22 Instruction breakpoint control: 0x40 .. 0x43

This register controls which logical cores may take an instruction breakpoint, and under which condition.

Bits	Perm	Init	Description	
31:24	RO	-	Reserved	
23:16	DRW	0	A bit for each thread in the machine allowing the breakpoint to be enabled individually for each thread.	
15:2	RO	-	Reserved	
1	DRW	0	When 0 break when PC == IBREAK_ADDR. When 1 = break when PC != IBREAK_ADDR.	
0	DRW	0	When 1 the instruction breakpoint is enabled.	

0x40 .. 0x43: Instruction breakpoint control

### B.23 Data watchpoint address 1: 0x50 .. 0x53

This set of registers contains the first address for the four data watchpoints.

**0x50 .. 0x53:** Data watchpoint address 1

Data hpoint	Bits	Perm	Init	Description
ress 1	31:0	DRW		Value.

### B.24 Data watchpoint address 2: 0x60 .. 0x63

This set of registers contains the second address for the four data watchpoints.

0x60 .. 0x63: Data watchpoint address 2

Data hpoint	Bits	Perm	Init	Description
dress 2	31:0	DRW		Value.

### B.25 Data breakpoint control register: 0x70 .. 0x73

This set of registers controls each of the four data watchpoints.

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	Bits	Perm	Init	Description
	31:24	RO	-	Reserved
	23:16	DRW	0	A bit for each thread in the machine allowing the breakpoint to be enabled individually for each thread.
<b>0x70 0x73:</b> Data breakpoint control	15:3	RO	-	Reserved
	2	DRW	0	When 1 the breakpoints will be be triggered on loads.
	1	DRW	0	Determines the break condition: $0 = A AND B$ , $1 = A OR B$ .
register	0	DRW	0	When 1 the instruction breakpoint is enabled.

#### B.26 Resources breakpoint mask: 0x80 .. 0x83

This set of registers contains the mask for the four resource watchpoints.

0x80 0x83: Resources				
breakpoint	Bits	Perm	Init	Description
mask	31:0	DRW		Value.

### B.27 Resources breakpoint value: 0x90 .. 0x93

This set of registers contains the value for the four resource watchpoints.

Ox90 0x93: Resources breakpoint     Bits     Perm     Init     Description				
breakpoint	Bits	Perm	Init	Description
value	31:0	DRW		Value.

### B.28 Resources breakpoint control register: 0x9C .. 0x9F

This set of registers controls each of the four resource watchpoints.

	Bits	Perm	Init	Description
<b>0x9C 0x9F:</b> Resources breakpoint control	31:24	RO	-	Reserved
	23:16	DRW	0	A bit for each thread in the machine allowing the breakpoint to be enabled individually for each thread.
	15:2	RO	-	Reserved
	1	DRW	0	When 0 break when condition A is met. When 1 = break when condition B is met.
register	0	DRW	0	When 1 the instruction breakpoint is enabled.





## C Tile Configuration

The xCORE Tile control registers can be accessed using configuration reads and writes (use write\_tile\_config\_reg(tileref, ...) and read\_tile\_config\_reg(tileref,  $\rightarrow$  ...) for reads and writes).

Number	Perm	Description	
0x00	CRO	Device identification	
0x01	CRO	xCORE Tile description 1	
0x02	CRO	xCORE Tile description 2	
0x04	CRW	Control PSwitch permissions to debug registers	
0x05	CRW	Cause debug interrupts	
0x06	CRW	xCORE Tile clock divider	
0x07	CRO	Security configuration	
0x20 0x27	CRW	Debug scratch	
0x40	CRO	PC of logical core 0	
0x41	CRO	PC of logical core 1	
0x42	CRO	PC of logical core 2	
0x43	CRO	PC of logical core 3	
0x44	CRO	PC of logical core 4	
0x45	CRO	PC of logical core 5	
0x46	CRO	PC of logical core 6	
0x47	CRO	PC of logical core 7	
0x60	CRO	SR of logical core 0	
0x61	CRO	SR of logical core 1	
0x62	CRO	SR of logical core 2	
0x63	CRO	SR of logical core 3	
0x64	CRO	SR of logical core 4	
0x65	CRO	SR of logical core 5	
0x66	CRO	SR of logical core 6	
0x67	CRO	SR of logical core 7	

Figure 32: Summary

### C.1 Device identification: 0x00

This register identifies the xCORE Tile

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	Bits	Perm	Init	Description
	31:24	CRO		Processor ID of this XCore.
0x00:	23:16	CRO		Number of the node in which this XCore is located.
Device	15:8	CRO		XCore revision.
identification	7:0	CRO		XCore version.

### C.2 xCORE Tile description 1: 0x01

This register describes the number of logical cores, synchronisers, locks and channel ends available on this xCORE tile.

Bits	Perm	Init	Description	
31:24	CRO		Number of channel ends.	
23:16	CRO		Number of the locks.	
15:8	CRO		Number of synchronisers.	
7:0	RO	-	Reserved	

### C.3 xCORE Tile description 2: 0x02

This register describes the number of timers and clock blocks available on this xCORE tile.

0x02: xCORE Tile description 2

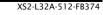
0x01: xCORE Tile description 1

	Bits	Perm	Init	Description
x02:	31:16	RO	-	Reserved
Tile	15:8	CRO		Number of clock blocks.
on 2	7:0	CRO		Number of timers.

### C.4 Control PSwitch permissions to debug registers: 0x04

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This register can be used to control whether the debug registers (marked with permission CRW) are accessible through the tile configuration registers. When this bit is set, write -access to those registers is disabled, preventing debugging of the xCORE tile over the interconnect.



0x04: Control PSwitch permissions to debug registers

Bits	Perm	Init	Description
31	CRW	0	When 1 the PSwitch is restricted to RO access to all CRW registers from SSwitch, XCore(PS_DBG_Scratch) and JTAG
30:1	RO	-	Reserved
0	CRW	0	When 1 the PSwitch is restricted to RO access to all CRW registers from SSwitch

### C.5 Cause debug interrupts: 0x05

This register can be used to raise a debug interrupt in this xCORE tile.

0x05: Cause debug interrupts

	Bits	Perm	Init	Description
	31:2	RO	-	Reserved
	1	CRW	0	1 when the processor is in debug mode.
I	0	CRW	0	Request a debug interrupt on the processor.

### C.6 xCORE Tile clock divider: 0x06

This register contains the value used to divide the PLL clock to create the xCORE tile clock. The divider is enabled under control of the tile control register

0x06: xCORE Tile clock divider

Bits	Perm	Init	Description	
31	CRW	0	Clock disable. Writing '1' will remove the clock to the tile.	
30:16	RO	-	Reserved	
15:0	CRW	0	Clock divider.	

### C.7 Security configuration: 0x07

Copy of the security register as read from OTP.

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	Bits	Perm	Init	Description	
	31	CRO		Disables write permission on this register	
	30:15	RO	-	Reserved	
	14	CRO		Disable access to XCore's global debug	
	13	RO	-	Reserved	
	12	CRO		lock all OTP sectors	
	11:8	CRO		lock bit for each OTP sector	
	7	CRO		Enable OTP reduanacy	
	6	RO	-	Reserved	
	5	CRO		Override boot mode and read boot image from OTP	
- -	4	CRO		Disable JTAG access to the PLL/BOOT configuration registers	
у: У	3:1	RO	-	Reserved	
n	0	CRO		Disable access to XCore's JTAG debug TAP	

0x07 Security configuration

### C.8 Debug scratch: 0x20 .. 0x27

A set of registers used by the debug ROM to communicate with an external debugger, for example over the switch. This is the same set of registers as the Debug Scratch registers in the processor status.

0x20 .. 0x27: Debug scratch

<b>0x27:</b> Debug	Bits	Perm	Init	Description
cratch	31:0	CRW		Value.

### C.9 PC of logical core 0: 0x40

Value of the PC of logical core 0.

0x40 PC of logical core 0

<b>)x40:</b> gical	Bits	Perm	Init	Description
ore 0	31:0	CRO		Value.

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### C.10 PC of logical core 1: 0x41

Value of the PC of logical core 1.



**0x41:** PC of logical core 1

Bits	Perm	Init	Description
31:0	CRO		Value.

### C.11 PC of logical core 2: 0x42

Value of the PC of logical core 2.

0x42: PC of logical core 2

Bits	Perm	Init	Description
31:0	CRO		Value.

### C.12 PC of logical core 3: 0x43

Value of the PC of logical core 3.

0x43:				
PC of logical	Bits	Perm	Init	Description
core 3	31:0	CRO		Value.

### C.13 PC of logical core 4: 0x44

Value of the PC of logical core 4.

**0x44** PC of logical core 4

<b>0x44:</b> ogical	Bits	Perm	Init	Description
core 4	31:0	CRO		Value.

### C.14 PC of logical core 5: 0x45

Value of the PC of logical core 5.

**0x45:** PC of logical core 5

Bits	Perm	Init	Description
31:0	CRO		Value.

Bits

31:0

### C.15 PC of logical core 6: 0x46

Value of the PC of logical core 6.

**0x46:** PC of logical core 6

 Perm
 Init
 Description

 CRO
 Value.

### C.16 PC of logical core 7: 0x47

Value of the PC of logical core 7.

0x47 PC of logical core 7

0x47: gical	Bits	Perm	Init	Description
ore 7	31:0	CRO		Value.

### C.17 SR of logical core 0: 0x60

Value of the SR of logical core 0

**0x60:** SR of logical core 0

<b>0x60:</b> ogical	Bits	Perm	Init	Description
ore 0	31:0	CRO		Value.

### C.18 SR of logical core 1: 0x61

Value of the SR of logical core 1

**0x61** SR of logical core 1

51: al	Bits	Perm	Init	Description
1	31:0	CRO		Value.

### C.19 SR of logical core 2: 0x62

Value of the SR of logical core 2



0x62: SR of logical core 2

Bits	Perm	Init	Description
31:0	CRO		Value.

### C.20 SR of logical core 3: 0x63

Value of the SR of logical core 3

0x63: SR of logical core 3

Bits	Perm	Init	Description
31:0	CRO		Value.

### C.21 SR of logical core 4: 0x64

Value of the SR of logical core 4

0x64:				
SR of logical	Bits	Perm	Init	Description
core 4	31:0	CRO		Value.

### C.22 SR of logical core 5: 0x65

Value of the SR of logical core 5

0x( SR of logi cor

<b>x65:</b> gical	Bits	Perm	Init	Description
re 5	31:0	CRO		Value.

### C.23 SR of logical core 6: 0x66

Value of the SR of logical core 6

0x66: SR of logical core 6

Bits	Perm	Init	Description
31:0	CRO		Value.

### C.24 SR of logical core 7: 0x67

Value of the SR of logical core 7

0x67:				
SR of logical	Bits	Perm	Init	Description
core 7	31:0	CRO		Value.



### **D** Node Configuration

The digital node control registers can be accessed using configuration reads and writes (use write\_node\_config\_reg(device, ...) and read\_node\_config\_reg(device,  $\rightarrow$  ...) for reads and writes).

Number	Perm	Description
0x00	RO	Device identification
0x01	RO	System switch description
0x04	RW	Switch configuration
0x05	RW	Switch node identifier
0x06	RW	PLL settings
0x07	RW	System switch clock divider
0x08	RW	Reference clock
0x09	R	System JTAG device ID register
0x0A	R	System USERCODE register
0x0C	RW	Directions 0-7
0x0D	RW	Directions 8-15
0x10	RW	DEBUG_N configuration, tile 0
0x11	RW	DEBUG_N configuration, tile 1
0x1F	RO	Debug source
0x20 0x28	RW	Link status, direction, and network
0x40 0x47	RO	PLink status and network
0x80 0x88	RW	Link configuration and initialization
0xA0 0xA7	RW	Static link configuration

Figure 33: Summary

### D.1 Device identification: 0x00

This register contains version and revision identifiers and the mode-pins as sampled at boot-time.

	Bits	Perm	Init	Description
	31:24	RO	-	Reserved
0x00:	23:16	RO		Sampled values of BootCtl pins on Power On Reset.
Device	15:8	RO		SSwitch revision.
ntification	7:0	RO		SSwitch version.

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identi

### D.2 System switch description: 0x01

This register specifies the number of processors and links that are connected to this switch.

0x01 System switch description

	Bits	Perm	Init	Description
-	31:24	RO	-	Reserved
l:	23:16	RO		Number of SLinks on the SSwitch.
h	15:8	RO		Number of processors on the SSwitch.
n	7:0	RO		Number of processors on the device.

### D.3 Switch configuration: 0x04

This register enables the setting of two security modes (that disable updates to the PLL or any other registers) and the header-mode.

Bits	Perm	Init	Description	
31	RW	0	0 = SSCTL registers have write access. $1 = SSCTL$ registers can not be written to.	
30:9	RO	-	Reserved	
8	RW	0	0 = PLL_CTL_REG has write access. 1 = PLL_CTL_REG can not be written to.	
7:1	RO	-	Reserved	
0	RW	0	0 = 2-byte headers, $1 = 1$ -byte headers (reset as 0).	

**0x04:** Switch configuration

### D.4 Switch node identifier: 0x05

This register contains the node identifier.

0x05
Switch node
identifier

0x05:	Bits	Perm	Init	Description
node	31:16	RO	-	Reserved
ntifier	15:0	RW	0	The unique ID of this node.

### D.5 PLL settings: 0x06

An on-chip PLL multiplies the input clock up to a higher frequency clock, used to clock the I/O, processor, and switch, see Oscillator. Note: a write to this register will cause the tile to be reset.

Bits	Perm	Init	Description
31	RW		If set to 1, the chip will not be reset
30	RW		If set to 1, the chip will not wait for the PLL to re-lock. Only use this if a gradual change is made to the PLL
29	DW		If set to 1, set the PLL to be bypassed
28	DW		If set to 1, set the boot mode to boot from JTAG
27:26	RO	-	Reserved
25:23	RW		Output divider value range from 0 (8'h0) to 7 (8'h7). OD value.
22:21	RO	-	Reserved
20:8	RW		Feedback multiplication ratio, range from 0 (8'h0) to 4095 (8'h3FF). F value.
7	RO	-	Reserved
6:0	RW		Oscilator input divider value range from 0 (8'h0) to 63 (8'h3F). R value.

0x06: PLL settings

### D.6 System switch clock divider: 0x07

Sets the ratio of the PLL clock and the switch clock.

0x07 System switch clock divider

	Bits	Perm	Init	Description
n k	31:16	RO	-	Reserved
r	15:0	RW	0	SSwitch clock generation

### D.7 Reference clock: 0x08

Sets the ratio of the PLL clock and the reference clock used by the node.

0x08:	Bits	Perm	Init	Description
Reference clock	31:16	RO	-	Reserved
	15:0	RW	3	Software ref. clock divider

### D.8 System JTAG device ID register: 0x09

**0x09**: System JTAG device ID register

	Bits	Perm	Init	Description
-	31:28	RO		
<b>9:</b> G	27:12	RO		
D	11:1	RO		
er	0	RO		

### D.9 System USERCODE register: 0x0A

**0x0A** System USERCODE register

A: n	Bits	Perm	Init	Description
E	31:18	RO		JTAG USERCODE value programmed into OTP SR
er	17:0	RO		metal fixable ID code

### D.10 Directions 0-7: 0x0C

This register contains eight directions, for packets with a mismatch in bits 7..0 of the node-identifier. The direction in which a packet will be routed is goverened by the most significant mismatching bit.

Bits	Perm	Init	Description
31:28	RW	0	The direction for packets whose dimension is 7.
27:24	RW	0	The direction for packets whose dimension is 6.
23:20	RW	0	The direction for packets whose dimension is 5.
19:16	RW	0	The direction for packets whose dimension is 4.
15:12	RW	0	The direction for packets whose dimension is 3.
11:8	RW	0	The direction for packets whose dimension is 2.
7:4	RW	0	The direction for packets whose dimension is 1.
3:0	RW	0	The direction for packets whose dimension is 0.

0x0C: Directions 0-7

### D.11 Directions 8-15: 0x0D

This register contains eight directions, for packets with a mismatch in bits 15..8 of the node-identifier. The direction in which a packet will be routed is goverened by the most significant mismatching bit.

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	Bits	Perm	Init	Description
	31:28	RW	0	The direction for packets whose dimension is F.
	27:24	RW	0	The direction for packets whose dimension is E.
	23:20	RW	0	The direction for packets whose dimension is D.
	19:16	RW	0	The direction for packets whose dimension is C.
	15:12	RW	0	The direction for packets whose dimension is B.
0x0D:	11:8	RW	0	The direction for packets whose dimension is A.
Directions	7:4	RW	0	The direction for packets whose dimension is 9.
8-15	3:0	RW	0	The direction for packets whose dimension is 8.

### D.12 DEBUG\_N configuration, tile 0: 0x10

Configures the behavior of the DEBUG\_N pin.

0x1 DEBUG\_N co figuratio tile

	Bits	Perm	Init	Description
10: on-	31:2	RO	-	Reserved
on,	1	RW	0	Set 1 to enable GlobalDebug to generate debug request to XCore.
e 0	0	RW	0	Set 1 to enable inDebug bit to drive GlobalDebug.

### D.13 DEBUG\_N configuration, tile 1: 0x11

Configures the behavior of the DEBUG\_N pin.

0x1 DEBUG\_N co figuratio tile

	Bits	Perm	Init	Description
1: 0n-	31:2	RO	-	Reserved
on,	1	RW	0	Set 1 to enable GlobalDebug to generate debug request to XCore.
21	0	RW	0	Set 1 to enable inDebug bit to drive GlobalDebug.

### D.14 Debug source: 0x1F

Contains the source of the most recent debug event.

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Bits	Perm	Init	Description
31:5	RO	-	Reserved
4	RW		If set, external pin, is the source of last GlobalDebug event.
3:2	RO	-	Reserved
1	RW		If set, XCore1 is the source of last GlobalDebug event.
0	RW		If set, XCore0 is the source of last GlobalDebug event.

**0x1F:** Debug source

### D.15 Link status, direction, and network: 0x20 .. 0x28

These registers contain status information for low level debugging (read-only), the network number that each link belongs to, and the direction that each link is part of. The registers control links 0..7.

Bits	Perm	Init	Description
31:26	RO	-	Reserved
25:24	RO		Identify the SRC_TARGET type 0 - SLink, 1 - PLink, 2 - SSCTL, 3 - Undefine.
23:16	RO		When the link is in use, this is the destination link number to which all packets are sent.
15:12	RO	-	Reserved
11:8	RW	0	The direction that this link operates in.
7:6	RO	-	Reserved
5:4	RW	0	Determines the network to which this link belongs, reset as 0.
3	RO	-	Reserved
2	RO		1 when the current packet is considered junk and will be thrown away.
1	RO		1 when the dest side of the link is in use.
0	RO		1 when the source side of the link is in use.

0x20 .. 0x28: Link status, direction, and network

### D.16 PLink status and network: 0x40 .. 0x47

These registers contain status information and the network number that each processor-link belongs to.

Bits	Perm	Init	Description
31:26	RO	-	Reserved
25:24	RO		Identify the SRC_TARGET type 0 - SLink, 1 - PLink, 2 - SSCTL, 3 - Undefine.
23:16	RO		When the link is in use, this is the destination link number to which all packets are sent.
15:6	RO	-	Reserved
5:4	RW	0	Determines the network to which this link belongs, reset as 0.
3	RO	-	Reserved
2	RO		1 when the current packet is considered junk and will be thrown away.
1	RO		1 when the dest side of the link is in use.
0	RO		1 when the source side of the link is in use.

**0x40 .. 0x47:** PLink status and network

### D.17 Link configuration and initialization: 0x80 .. 0x88

These registers contain configuration and debugging information specific to external links. The link speed and width can be set, the link can be initialized, and the link status can be monitored. The registers control links 0..7.

Bits	Perm	Init	Description
31	RW		Write to this bit with '1' will enable the XLink, writing '0' will disable it. This bit controls the muxing of ports with overlapping xlinks.
30	RW	0	0: operate in 2 wire mode; 1: operate in 5 wire mode
29:28	RO	-	Reserved
27	RO		Rx buffer overflow or illegal token encoding received.
26	RO	0	This end of the xlink has issued credit to allow the remote end to transmit
25	RO	0	This end of the xlink has credit to allow it to transmit.
24	WO		Clear this end of the xlink's credit and issue a HELLO token.
23	WO		Reset the receiver. The next symbol that is detected will be the first symbol in a token.
22	RO	-	Reserved
21:11	RW	0	Specify min. number of idle system clocks between two contin- uous symbols witin a transmit token -1.
10:0	RW	0	Specify min. number of idle system clocks between two contin- uous transmit tokens -1.

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0x80 .. 0x88: Link configuration and initialization

### D.18 Static link configuration: 0xA0 .. 0xA7

These registers are used for static (ie, non-routed) links. When a link is made static, all traffic is forwarded to the designated channel end and no routing is attempted. The registers control links C, D, A, B, G, H, E, and F in that order.

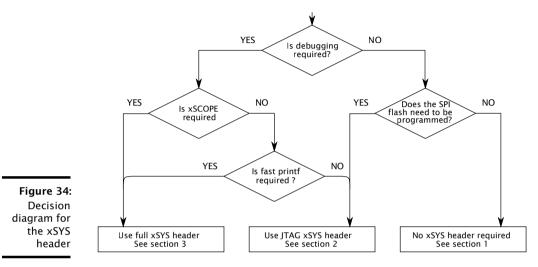
Bits	Perm	Init	Description	
31	RW	0	nable static forwarding.	
30:9	RO	-	Reserved	
8	RW	0	The destination processor on this node that packets received in static mode are forwarded to.	
7:5	RO	-	Reserved	
4:0	RW	0	The destination channel end on this node that packets received in static mode are forwarded to.	

**0xA0 .. 0xA7:** Static link configuration



### E JTAG, xSCOPE and Debugging

If you intend to design a board that can be used with the XMOS toolchain and xTAG debugger, you will need an xSYS header on your board. Figure 34 shows a decision diagram which explains what type of xSYS connectivity you need. The three subsections below explain the options in detail.



### E.1 No xSYS header

The use of an xSYS header is optional, and may not be required for volume production designs. However, the XMOS toolchain expects the xSYS header; if you do not have an xSYS header then you must provide your own method for writing to flash/OTP and for debugging.

### E.2 JTAG-only xSYS header

The xSYS header connects to an xTAG debugger, which has a 20-pin 0.1" female IDC header. The design will hence need a male IDC header. We advise to use a boxed header to guard against incorrect plug-ins. If you use a 90 degree angled header, make sure that pins 2, 4, 6, ..., 20 are along the edge of the PCB.

Connect pins 4, 8, 12, 16, 20 of the xSYS header to ground, and then connect:

- ▶ TDI to pin 5 of the xSYS header
- TMS to pin 7 of the xSYS header
- TCK to pin 9 of the xSYS header
- DEBUG\_N to pin 11 of the xSYS header

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TDO to pin 13 of the xSYS header

The RST\_N net should be open-drain, active-low, and have a pull-up to VDDIO.

### E.3 Full xSYS header

For a full xSYS header you will need to connect the pins as discussed in Section E.2, and then connect a 2-wire xCONNECT Link to the xSYS header. The links can be found in the Signal description table (Section 4): they are labelled XL0, XL1, etc in the function column. The 2-wire link comprises two inputs and outputs, labelled  ${}^{1}_{out}$ ,  ${}^{0}_{out}$ ,  ${}^{0}_{in}$ , and  ${}^{1}_{in}$ . For example, if you choose to use XL0 for xSCOPE I/O, you need to connect up XL0 ${}^{1}_{out}$ , XL0 ${}^{0}_{out}$ , XL0 ${}^{1}_{in}$ , XL0 ${}^{1}_{in}$  as follows:

- XL0<sup>1</sup><sub>out</sub> (X0D43) to pin 6 of the xSYS header with a 33R series resistor close to the device.
- XL0<sup>0</sup><sub>out</sub> (X0D42) to pin 10 of the xSYS header with a 33R series resistor close to the device.
- ▶ XL0<sup>0</sup><sub>in</sub> (X0D41) to pin 14 of the xSYS header.
- >  $XLO_{in}^{1}$  (X0D40) to pin 18 of the xSYS header.

### F Schematics Design Check List

✓ This section is a checklist for use by schematics designers using the XL232-512-FB374. Each of the following sections contains items to check for each design.

### F.1 Power supplies

- □ VDDIO and OTP\_VCC supply is within specification before the VDD (core) supply is turned on. Specifically, the VDDIO and OTP\_VCC supply is within specification before VDD (core) reaches 0.4V (Section 11).
- The VDD (core) supply ramps monotonically (rises constantly) from 0V to its final value (0.95V 1.05V) within 10ms (Section 11).
- The VDD (core) supply is capable of supplying 1400 mA (Section 11 and Figure 19).
- PLL\_AVDD is filtered with a low pass filter, for example an RC filter, see Section 11

### F.2 Power supply decoupling

- ☐ The design has multiple decoupling capacitors per supply, for example at least four0402 or 0603 size surface mount capacitors of 100nF in value, per supply (Section 11).
- A bulk decoupling capacitor of at least 10uF is placed on each supply (Section 11).

### F.3 Power on reset

The RST\_N and TRST\_N pins are asserted (low) during or after power up. The device is not used until these resets have taken place.

### F.4 Clock

- The CLK input pin is supplied with a clock with monotonic rising edges and low jitter.
- Pins MODE0 and MODE1 are set to the correct value for the chosen oscillator frequency. The MODE settings are shown in the Oscillator section, Section 7. If you have a choice between two values, choose the value with the highest multiplier ratio since that will boot faster.

#### F.5 Boot

- □ The device is connected to a QSPI flash for booting, connected to X0D01, X0D04..X0D07, and X0D10 (Section 8). If not, you must boot the device through OTP or JTAG, or set it to boot from SPI and connect a SPI flash.
- ☐ The Flash that you have chosen is supported by **xflash**, or you have created a specification file for it.

### F.6 JTAG, XScope, and debugging

- $\Box$  You have decided as to whether you need an XSYS header or not (Section E)
- □ If you have not included an XSYS header, you have devised a method to program the SPI-flash or OTP (Section E).

#### F.7 GPIO

- You have not mapped both inputs and outputs to the same multi-bit port.
- Pins X0D04, X0D05, X0D06, and X0D07 are output only and are, during and after reset, pulled high and low appropriately (Section 8)
- Pins X2D04, X2D05, X2D06 and X2D07 are output only and during and after reset, X2D06 is pulled high and X2D04, X2D05, and X2D07 are pulled low (Section 8)

### F.8 Multi device designs

Skip this section if your design only includes a single XMOS device.

- $\Box$  One device is connected to a QSPI or SPI flash for booting.
- Devices that boot from link have, for example, X0D06 pulled high and have link XL0 connected to a device to boot from (Section 8).

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### G PCB Layout Design Check List

This section is a checklist for use by PCB designers using the XS2-L32A-512-FB374. Each of the following sections contains items to check for each design.

### G.1 Ground Plane

- Each ground ball has a via to minimize impedance and conduct heat away from the device. (Section 11.2)
- Other than ground vias, there are no (or only a few) vias underneath or closely around the device. This create a good, solid, ground plane.

### G.2 Power supply decoupling

- The decoupling capacitors are all placed close to a supply pin (Section 11).
- $\Box$  The decoupling capacitors are spaced around the device (Section 11).
- The ground side of each decoupling capacitor has a direct path back to the center ground of the device.

### G.3 PLL\_AVDD

The PLL\_AVDD filter (especially the capacitor) is placed close to the PLL\_AVDD pin (Section 11).

### H Associated Design Documentation

Document Title	Information	Document
Estimating Power Consumption For XS1-L Devices	Power consumption	Link
XMOS Programming Guide	Timers, ports, clocks, cores and channels	Link
xTIMEcomposer User Guide	Compilers, assembler and linker/mapper	Link
	Timing analyzer, xScope, debugger	
	Flash and OTP programming utilities	

### I Related Documentation

Document Title	Information	Document
xCORE200: the XMOS XS2 Architecture	ISA manual	Link
I/O timings for xCORE200	Port timings	Link
xCONNECT Architecture	Link, switch and system information	Link
XS1-L Link Performance and Design Guidelines	Link timings	Link
XS1-L Clock Frequency Control	Advanced clock control	Link
XS1-L Active Power Conservation	Low-power mode during idle	Link

#### J **Revision History**

Date	Description	
2015-03-20	Preliminary release	
2015-04-14	Added RST to pins to be pulled hard, and removed reference to TCK from Errata	
	Removed TRST_N references in packages that have no TRST_N	
2015-05-06	Removed references to DEBUG_N	
2015-07-09	Updated electrical characteristics - Section 12	
2015-08-27	Updated part marking and product code - Section 14	
2015-11-23	Updated status of X2D04, X2D05, X2D06, X2D07 during boot - Section 8	
	Updated Schematics Design Checklist: GPIO for X2D04, X2D05, X2D06, X2D07 during boot - Section F	
2015-12-18	Clarified connectivity of internal and external xCONNECT links - Sections 3 and 4	
	Made pin names canonical - Sections 3 and 4	
	Updated JTAG diagram - Section 10	
	Removed references to 400MHz parts - Section 12	
2016-01-05	Updated signal tables to use VDDIO - Section 4	
	Updated IDD value - Section 12	
	Updated land pattern description - Section 11.1	
2016-04-20	Typical internal pull-up and pull down current diagrams added - Section 12	
2017-09-19	Added Absolute Maximum Ratings - Section 12.1	
	Reference document links updated - Section H	
2018-03-23	Incorrect IDCODE return value updated - Section 10	

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